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An Intelligent Location Monitoring System

Deliverable D2.2

Hardware Requirements: Platform and Devices

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AAL-2016 – Living with Dementia

Document Control

This deliverable is the responsibility of the Work Package Leader. It is subject to internal review and formal authorisation procedures in line with ISO 9001 international quality standard procedures.

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1.0	01/10/2020	Gary McManus	Approved version release.

Executive Summary

Objectives

This deliverable relies on a survey that provides a critical source of data and insights about a number of existing Assistive Technologies (ATs) and supportive services and potential hardware that can be potentially used to improve the quality of life of the ageing People with Dementia (PwD).

The main goals of this deliverable are including:

- Reviewing, identifying, and documenting some commercially available ATs (with multiple and single capabilities) and supportive services that can help ensuring healthy lives and promote well-being for PwD.
- To nominate the best items of the identified ATs and supportive services (based on considered features) and using them as a base for designing and customizing a set of wearable technologies and supportive services for PwD under CARELINK project.
- To survey the state-of-the-art on hardware, including System-on-a-Chip integrations that include localization, communication, and sensing features, compatible with the incorporation in a sensor pack.
- To benefit from the findings of previous studies in setting the components of the sensor pack prototypes.

Results

This Deliverable addresses 86 potential ATs (39 technologies with multiple capabilities and 47 technologies with single capability), 15 supportive services, and 75 hardware that each of which (either alone or in conjunction) has potential application in assisting PwD in different circumstances. The results of this work provide an insight to the types, competitive capabilities, and unique features of the commercially available technologies and services which can lead to some possible solutions to better deal with day–to–day realities of dementia.

Among the five defined classes (cognitive enhancement, environmental, physiological, functional, Teleinformation), cognitive enhancement was the most addressed issue for both ATs with single capability and supportive services. And functional was the most focused matter for ATs with multiple capabilities in reviewed studies.

The identified hardware with communication, localization and sensing capabilities can give aid for designing and developing wearable technologies that are customized with low energy consumption, low-cost, and smallsized features in response to the specific needs of PwD.

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1 INTRODUCTION

The number of people living with dementia is rising at an unprecedented rate, and no country will be spared. An approach to this emerging crisis is the development and deployment of intelligent ATs and supportive services that compensate for the specific physical and cognitive deficits of older adults with dementia, and thereby also reduce caregivers burden. Wearable technologies (e.g. smart phones and smartwatches), as example of ATs, trigger questions about how we can deliver better services, create efficiencies and improve the quality of life for PwD. Furthermore, systematic monitoring and evaluation of health and social care data provide evidence for policy development and service delivery, improve accessibility to and coordination of care for PwD. As such, adding specific hardware to ATs can expand their functions and would resolve many issues faced by PwD patients and would lead to improving their health, and safety.

Given that, this manuscript performs a review to document some available and potential ATs and supportive services to be used for both precise locations monitoring and tracking movement, and also checking the physiological signals of PwD body. Therefore, this deliverable identifies the:

- 86 commercially available ATs and 15 different supportive services (among the others in the literature) which might find role in caring people suffering from dementia. They are classified in different classes and sub-classes (based on their capabilities and features) to make their understanding and evaluation easy.
- 2. 75 supportive hardware (e.g. wireless sensors, devices, chips and microchips) that have applications for both precise location monitoring and the tracking of physiological signals. In this regard the type of hardware, their specific features and capabilities (e.g. energy consumption, price, size), and the kind of tasks that they can perform (e.g. localization and communication) are analysed.

The results of the state-of-the-art lead to identifying group of potential ATs, supportive services, and supportive hardware which in turn can deliver possible solutions for specific needs of PwD. The rest of this deliverable is structured as follows: Section 2 addresses the used abbreviations and acronyms. Section 3 presents the state of the art of identified ATs and supportive services. Section 4 explains the supportive hardware that in integration with ATs can add new functions. The application and development of ATs such as smartwatch and smartphone are also explained in this section. The concluding remarks are presented in section 5.

2 ABBREVIATIONS AND ACRONYMS

Abbreviation	Description
AT	Assistive Technology
PwD	Person/People with Dementia
ECG	Electrocardiogram
BLE	Bluetooth Low Energy
GNSS	Global Navigation Satellite System
GPS	Global Positioning System
GSM	Global System for Mobile communications
LoRa	Long Range (Long Range Wide Area Network communications)
LTE	Long-Term Evolution mobile communications
MQTT	Message Queue Telemetry Transport
TTFF	Time to First Fix

STATE OF THE ART 3

Those suffering from dementia exhibit impairments of memory, thought, and reasoning. It has been recognised that deployment of technological solutions and supportive services to address such impairments may have a major positive impact on the quality of life and can be used to help perform daily life activities hence maintaining a level of independence. On the other hand, neither decisive treatment nor effective medicines have already introduced for dementia. This work is motivated by the expanding demand and limited supply of long-term personal care for PwD, and supportive technologis and services as an alternative. Given that, this section presents an overview of the current state of the art of some identified and available ATs and supportive services that each have potential to provide specific support for PwD in particular circumstances.

3.1 Identified Assistive Technologies

3.1.1 Assistive Technologies with Multiple Capabilities

Various ATs can be configured to work together or independently as sensing modalities of PwD physical behaviour. Among the promising technologies for the purpose of this deliverable, our review of the literature identified 39 ATs with multiple capabilities, see Table 2. Based on the specific features and characteristics they are classified in five main classes namely, cognitive enhancement sensors, environmental sensors, physiological sensors, functional sensors, and tele information devices. According to the task/s that they can fulfil, each class is divided into some sub-classes. The proposed classes and sub-classes for identified ATs with multiple capabilities are presented in Table 1.

Table 1 – Proposed classes and sub-classes for identified ATs with multiple capabilities.

Table	Table 2 – Identified ATs with multiple capabilities. Proposed classes and sub-classes for identified ATs with multiple capabilities													
	itive en ensors/			Environ sens			ysiologi sensors				unction sensors			Tele info devices
Capturing data from physical behaviors and communication	Support doing daily tasks	Tracking	Providing communication	Checking safety and generating alarm/alert	Controlling conditions of environment	Checking energy expenditure	Checking sleeping	Checking body condition	Monitoring activities	Checking performance	Tracking hand function	Detecting fall	Checking motion and/or gait	Telecare
	Identified ATs with multiple capabilities													

Idontified ATo with

CareMedia	Smart-carpet	PocketFinder	MagIC vest
COACH	NOTECASE	Spy Tec Mini GPS Tracker	Microsoft Sensecam
Mimamori-care system	Wandering Detection Algorithm	SPOT GEN3	CarePredict
Wearable and wireless camera system	ActionSLAM	GPS SmartSole	Sensor-derived physical activity
Physical activity monitor	Indoor Localization Network	Footprint by OwnFone	SIMBAD Project
Kognit	Nonintrusive pervasive computing model	Wearable NFC Wristband	Back-plaster sensor node
Sensor-based system	WearNET	MySOS from SkyGuard	low-cost fall intervention system
Complex Event Processing	SenSay	Mindme Alarm	Android Based Wearable Smart Locator Band
Buddi	Multi-accelerometer based systems	LESHP GPS Tr	Pervasive assistive solution
Ultra wideband system	iTraq	VTAM T-shirt	

3.1.2 Assistive Technologies with Single Capabilities

Organizer, executive and assistan

In Table 3, the same classification is followed for ATs with single capability. However, in this classification the class of tele information devices is omitted, since we could not find in the literature any potential AT with single capability that can be placed in this class. It is noteworthy that the four defined classes in this table have, in some cases, different sub-classes in comparison with the Table 1.

	Propose	d classes a	nd sub-cla	sses for ide	entified ATs wi	th single c	apability
-	tive enhance nsors/devic			nmental sors	Physiological sensors		Functional sensors

Controlling environmental

condition

 Table 3 – Proposed classes and sub-classes for identified ATs with single capability.

Detector contact and proximity

Totally, 47 ATs with single capability are identified from the literature. These technologies have only one
capability and can accomplish a single task. According to the features and characteristics, the identified ATs
with single capability are listed in Table 4.

Controlling body condition

Reminder

Tracking

Detecting fall

Detecting motion and gait

Improving human balance

Identified ATs with single capability				
Cognitive enhancement sensors/devices	Environmental sensors	Physiological sensors	Functional sensors	
Memory Glasses	Contact sensor	Bedwetting alarms	Motion detector	
MemoClip	Proximity detector	BodyMedia (SenseWear® Pro Armband)	Radiofrequency	
Cook's Collage	Voice activation sensors	Garmin Forerunner	VTT gait monitor	
Komihu	Light sensor	Medical mood ring	Displacement sensor	
Memofy	Temperature and heat sensor	Tadiran's MDkeeper	CareWatch	
IMP	Force sensor	Ciclosport Alpin	Fall detector	
Opportunity Knocks	Pressure sensor	Boardbug	Floor vibration-based fall detector	
Activity Compas	Door and window sensor	Sensvest	Accelerometers	
Trax	Leak and spill detector	OFSETH	Vibrating gel insoles	
Yepzon One Personal GPS Locator	Glass break detectors			
PAL	Vibration/ sound detectors			
PEAT	Electrical usage sensors			
ISAAC	Water/sewer usage sensor			
AutoMinder				
Integration of pervasive computing, big data processing and machine learning				
Calm computing and implicit guiding cues				

3.2 Identified Supportive Services

Dementia is a progressive syndrome that can affect a person's memory, thinking, orientation and comprehension, combined with deteriorating senses (sight, touch, taste, smell and hearing). It can cause huge changes in a person's life and in the lives of those around them.

To reduce the burden of dementia, there are different service providers around the word (national or international, governmental or private) that deliver variety of supports for PwD, their families, and carers. The total of 15 supportive services are identified and listed in Table 6.

The developed classification for the supportive services is nearly similar to the recommended classification for ATs in Table 1 and Table 3. But in this classification, there are some differences in terms of number of subclasses (either some are added or deleted). Furthermore, some sub-classes are introduced with different names, see Table 5. Except the similar addressed classes in this classification, one new class (named "type of care") is added to this table. This class is defined to indicate that in which place the service can be possibly

	Proposed classes and sub-classes for identified supportive services											
Type of care	Cognit	ive enhan	icement s	ervices		nmental vices		ological vices	Func	tional sei	rvices	Tele info devices
Indoor / outdoor	Capturing data from physical behaviors & communication	Support doing daily tasks	Tracking	Providing communication	Finding orientation and navigation	Reminding or altering events	Checking diaper	Checking body condition	Monitoring activities	Checking performance	Detecting fall	Telecare

Table 5 – Proposed classes and sub-classes for identified supportive services.

In order to maintain unity for the documented ATs and supportive services in this deliverable, nearly equal classification is considered (but the number of classes, sub-classes, and also the type of sub-classes are not exactly the same in all cases). It is believed that such classification not only can facilitate identifying and evaluating the considered ATs and supportive services, but also represents the most concerning issues in the context of monitoring the health, safety, and welfare of affected persons.

Identified supportive services						
Wearable device monitoring services (WDMS)	Reminder Service (RS)	Portable projection-based display system PiTaSu	Indoor residence monitoring mode			
Data Acquisition and Wireless Event Forwarding Service (DAWEFS)	Calm computing and implicit guiding cues	National emergency response service	Emergency rescue			

Table 6 – Identified supportive services.

Ambient Sensor Monitoring Service (ASMS)	Smart assistive living	PROACT	Remote monitoring mode
Initialization and caregiver support service (ICSS)	Smart wireless continence management system	Outdoor activity area monitoring	

3.3 Analysing Collected Data

In this section the identified ATs and supportive services are separately analysed. This analyse relies on the types and percentages of their application or consideration in reviewed references. Given the above-mentioned ATs with multiple functionalities it can be seen that among the five defined classes (cognitive enhancement sensors/devices, environmental sensors, physiological sensors, functional sensors, tele info devices), the most applied class is functional sensors group with (46.08%). It is followed with the class of cognitive enhancement sensors with (31.73%), the class of environmental sensors with (13.48%), and the class of physiological sensors with (7.13%). The class of tele information devices (with 1.58%) is the less applied group of technologies in this classification. The types and percentages of defined classes and sub-classes are illustrated in Figure 1.

From the findings of this classification it can be said that:

- The technologies and sensors that are designed to monitor PwD's activities and also to find and track his location are the most concerned technologies (in considered references).
- Those technologies and sensors that check the rate of energy expenditure, and track hand function do not receive attention as much as the others (in considered references).

In Figure 1, the types and percentages of proposed classes and sub-classes for the identified ATs with multiple functionalities are demonstrated.

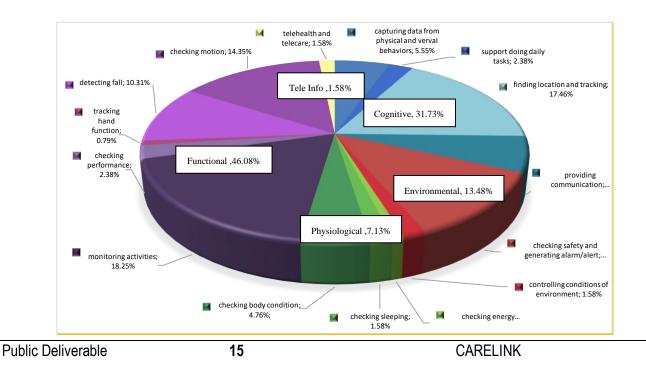


Figure 1. Types and percentages of proposed classes and sub-classes for technologies with multiple functionalities.

Taking into account the above classification for ATs with single functionalities, it can be seen that cognitive enhancement sensors are the most applied (34.04%), followed by environmental sensors (27.66%). The results also show that both physiological sensors and functional sensors received equal attention (16.15%). Among the sub-classes, sensors for controlling environmental condition with (21.27%), and sensors for controlling body condition with (19.15%) are respectively the most applied sensors. But, sensors for improving human balance with (2.13%s) are not under consideration as much as other addressed technologies.

In Figure 2, the types and percentages of proposed classes and sub-classes for the identified ATs with single functionality are demonstrated.

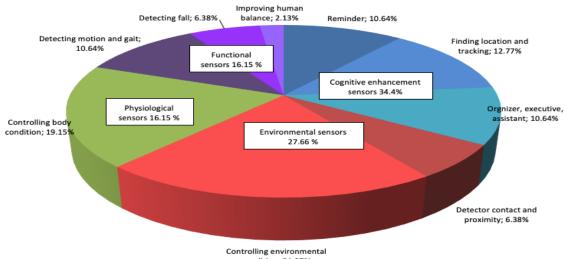




Figure 2. Types and percentages of proposed classes and sub-classes for technologies with single functionality.

As addressed in Table 2, 15 supportive services for PwD are identified. The majority of those considered references focused more on the issue of cognitive enhancement. Thus, this class has the highest percentage of application (35.48%) among the others while the physiological issues have the lowest degree (6.45%) of application. More detailed information is illustrated in Figure 3.

Given the considered classification, it can be concluded that:

- Services for finding location and tracking, and services for reminding or altering the events are equally the most applied services with (19.35%).
- Those services that provide communication, find orientation and navigation, check diaper, or check body condition, show the lowest percentage of application (3.22%).
- Some of the proposed services in Table 2 are made for indoor care and some for outdoor care. Their • analysis shows that among all 15 addressed services in this table, 9 services are developed for indoor care, 1 service for outdoor care, and 5 services for both purposes (indoor and outdoor care).

The types and percentages of proposed classes and sub-classes for the identified supportive services are demonstrated in Figure 3.

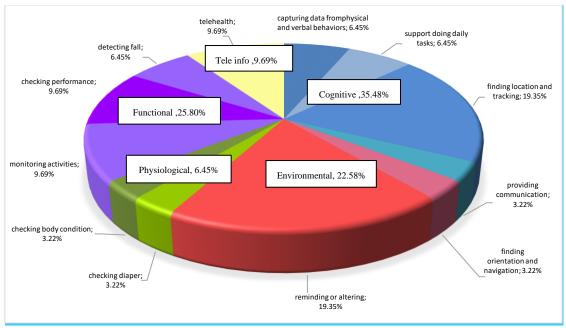


Figure 3. Types and percentages of proposed classes and sub-classes for the supportive services.

4 SUPPORTIVE HARDWARE

Advances in new age of supportive hardware (e.g. wireless sensors, devices, chips, and microchips) that are using for dementia has facilitated measuring variety of variables. As for instance, it has brought good opportunities for monitoring physical and environmental conditions. Furthermore, grouping and packing such kind of hardware and networking them with together can, for example, reform the way and speed of information gathering and also promote target yields and quality. Evidences show that the developed network has high potential, for example, to support location monitoring, building wireless communication, monitoring physical and physiological condition of patients (e.g., heart rate, oxygen saturation, temperature, blood pressure, etc.), accelerating the process, and transmitting the collected and proceed data in a timely fashion to some remote location without human intervention.

As such, attaching specific sensors on home, vehicles, body, or ATs not only could bring some possibilities for monitoring health and body conditions, but also could help collecting wide range of environmental data that can be used in detecting PwD's real-time location and current movements.

Given that, a number of suited hardware with communication, localization and sensing capabilities are identified and documented in this section to give aid for designing and developing customized wearable technologies in response to the specific needs of PwD.

4.1 Hardware Features

The requirement to have a sensor pack suitable for wearability with helpful features in assistance of PwD's biometrics checking and wandering detection (and possibly other additional dementia issues and side effects) justifies the need for:

A. Localization technology – helps reliable tracking of the PwD that can be used for route prediction,

B. Local communications – help continually accessing to device data (e.g. data from inside the PwD's home),

C. Mobile communication - help continually accessing to device data (e.g. data from outside the PwD's home),

D. *Sensors* – help collecting data from the PwD biometrics, and also forecasting common side effects of dementia such as wandering and accidental fall.

These needed technical features and technologies are explained in follow:

A. Localization

For localization and tracking the PwD, both GNSS and GPS are applied.

- *GNSS* (*Global Navigation Satellite System*) is an umbrella term for a system that provides signals from space that transmits navigation, positioning, timing data, and other services to GNSS receivers.
- *GPS*(*Global Positioning System*) is a space-based satellite navigation and precise-positioning tool that provides positioning, navigation, and timing (PNT) services in all weather conditions, anywhere in the world or near the Earth, 24 hours a day.

> GPS Specific Characteristics

- TTFF (Time to First Fix) refers to the time that GPS device/receiver needs to find the position. The TTFF involves three major scenarios: (a) Hot or standby: at this point the receiver has valid value of time, position, almanac, and ephemeris data which lead to a rapid acquisition of satellite signals. (b) Warm or normal: at this point the receiver can predict the current time within 20 seconds, the current position within 100 kilometres, and its velocity within 25 m/s, and it has valid almanac data. (c) Cold or factory: at this point the receiver does not have accurate prediction of its position, velocity, the time, or the visibility of any of the GPS satellites.
- *GPS accuracy* refers to the degree of closeness of indicated readings to the actual position. The accuracy of GPS data depends on several factors including, quality of the GPS receiver, satellite geometry, satellite signals, propagation delay, characteristics of the surroundings, internal clock errors, selective availability, etc.

B. Local Communication

For local communication and accessing device data from inside the PwD's home, both Wi-Fi and Bluetooth are applied.

- *Wi-Fi* is a wireless networking protocol that uses radio frequency signals and radio waves. It allows nearby devices such as, PCs, laptops, smart phones, tablet devices or printers to connect at high speed to the internet and each other without the need for a physical wired connection. There are three types of Wi-Fi or wireless protocols namely, long range (is measured in miles), medium range (is measured in tens or hundreds of feet), and short-range (is less than 10 feet).
- Bluetooth is an open wireless communication technology that is made for exchanging data through fixed and/or mobile electronic device (e.g., as mobile phones, computers, and peripherals). It is used for building personal area networks (PANs) specifically over short distances, close range, and low power communication.

C. Mobile Communication

For mobile communication and accessing device data from outside the PwD's home, both GSM and LTE are used.

- *GSM* (*Global System for Mobile communications*) is an international standard for developing a digital mobile communication system, and to describe the protocols for second-generation digital cellular networks used by mobile devices such as tablets.
- *LTE* (*Long Term Evolution*) is a standard for 4G wireless broadband technology that offers increased network capacity and speed to mobile device users, based on the GSM/EDGE and UMTS/HSPA technologies.

D. Sensors

In order to control the PwD's vital biometrics, the following four items are considered:

- *Heart rate* also known as pulse, is the speed of the heartbeat and the number of times per minute that the heart contracts. It is one of the important indicators and 'vital signs,' of health in the human body.
- *Temperature* human body temperature (known as Normothermia or Euthermia) is a measure of the body's ability to generate and/or get rid of heat. It varies by person, age, activity, and time of day.
- ECG (Electrocardiogram) is the process of recording and displaying the electrical signals, rate, rhythm, and muscular functions of the heart during a cardiac cycle to show whether it is working normally or not.

• *Accelerometer* – is defined as rate of change of velocity with respect to time. Accelerometer is an electromechanical device used to detect changes in gravitational acceleration and tilt in numerous devices by measuring the force associated with translational motion.

4.2 Considered Hardware Characteristics

- *Power consumption* refers to the actual electrical energy demand of device for operation.
- Size refers to the physical dimensions of device that can be measured as length, width, height.
- *Operating temperature* refers to the specified temperature range, at which the device operates effectively. This operating temperature ranges from a minimum, to a maximum, and outside which, the power supply may fail.
- *Price* refers to the amount of payment for buying the device.
- *Interface* refers to a system or device that connect those entities (e.g., boards, chips) using for interaction and communication. There are different communication protocols used in embedded systems including, USART, UART, RS232, USB, SPI, I2C, TTL, etc.

4.3 Identified Hardware

A total of 75 available and potential hardware (e.g. sensors, devices, chips, and microchips) are identified from the literature. They are listed in the following tables based on their application, and specific features and characteristics:

Identified GNSS and GPS devices						
Multi-GNSS Receiver Chip eRideOPUS 7Model ePV7010B	Multi-GNSS Receiver Chip eRideOPUS 7Model ePV7000B	A2200-A	Flora Wearable Ultimate GPS Module 1059			
МТК3339 (FGPMMOPA6H)	Trimble Copernicus II	Venus638FLPx-L 20Hz	BX305			
RXM-GPS-RM-B	7DLTS0075	UBX-M8230-CT				

Table 7 –	Identified	GNSS and	GPS	devices.

For the 11 devices addressed in Table 7, the following characteristics are considered: current consumption, supply voltage, power consumption, size, temperature, price, interface, accuracy, and TTFF. Among the devices, BX305 has the best accuracy, and UBX-M8230-CT has the lowest power consumption, size, and TTFF. See appendix (Table 7).

Table 8 – Identified Wi-Fi / Wireless devices.

Identified Wi-Fi / Wireless devices						
MOD-WIFI-ESP8266	ESP8285	ESP8266EX	CleO35-WiFi1			

RTL8710	88MW302	WE935B00	ST60-SIPT-C
Atheros AR9331	CC3100R11MRGCR	CC3100MOD R11 MAMOBR	

For the 11 devices addressed in Table 8, the following characteristics are considered: current consumption, supply voltage, power consumption, size, temperature, price, interface, and protocol. Among the devices, MOD-WIFI-ESP8266, ESP8285, and ESP8266EX have equally the smallest size, and 88MW302 has the lowest power consumption. See appendix (Table 8).

Table 9- Identified Bluetooth devices.

Identified Bluetooth devices						
RN4020-V/RMBEC133 ATBTLC1000A-MU-Y MKW30Z160VHM4 CC2560BYFVR						
CC2640R2FRGZT	CC2564BRVMR	nRF52810-QFAA-R	nRF8001-R2Q32-T			
nRF52832-QFAB-R	BLUENRG-132	SKB369A	BLE (ISP1807)			

For the 12 devices addressed in Table 9, the following characteristics are considered: current consumption, supply voltage, power consumption, size, temperature, price, interface, and protocol. Among the devices, ATBTLC1000A-MU-Y and CC2640R2FRGZT have equally the smallest size, and SKB369A has the lowest power consumption. See appendix (Table 9).

Table 10- Identified GSM and LTE devices.

Identified GSM and LTE devices					
FiPy Adafruit Feather 32u4 Particle Electron SIM7000E FONA SIM7000E SIM7000E SIM7000E					
Hologram Dash	SIM900 Quad Band GSM GPRS Shield	LinkIt ONE (-102030002)	SIM900 GSM/GPRS shield for Arduino		

For the 8 devices addressed in Table 10, the following characteristics are considered: current consumption, supply voltage, power consumption, size, temperature, price, interface, and protocol. Among the devices, FiPy has the lowest power consumption, and Particle Electron has the smallest size. See appendix (Table 10).

Table 11- Identified heart rate sensors.

Identified heart rate sensors					
BH1790GLC-E2	AD8232ACPZ-R7	PIC16F1779-E/PT	ATSAMB11-ZR210CA- ND		
SFH 7070	SFH 7051	SI1143-M01-GMR	AFE4403YZPT		

SparkFun Particle Sensor	 	
Breakout – MAX30105		

For the 9 devices addressed in Table 11, the following characteristics are considered: current consumption, supply voltage, power consumption, size, temperature, price, and interface. Among the devices, BH1790GLC-E2 has the smallest size, and PIC16F1779-E/PT has the lowest power consumption. See appendix (Table 11).

Table 12- Identified body temperature measuring sensors.

Identified body temperature measuring sensors								
MAX30205MTA+	MAX30205MTA+ Fever click (MIKROE-2554) BMP180 HDC2010YPAR							
TMP116NAIDRVR MLX90614ESF SI7051-A20-IM								

For the 7 devices addressed in Table 12, the following characteristics are considered: current consumption, supply voltage, power consumption, size, temperature, price, interface, and accuracy. Among the devices, TMP116NAIDRVR and SI7051-A20-IM have equally the smallest size, and TMP116NAIDRVR has also the lowest power consumption. See appendix (Table 12).

Table 13- Identified measuring ECG sensors.

Identified measuring ECG sensors									
AD8232ACPZ-R7 AD8232ACPZ-RL MAX86150EFF+T MAX30003CTI+									
PS25205B	PS25251	Si1171	ADS1298RIZXGR						
Micro ECG	Micro ECG								

For the 9 devices addressed in Table 13, the following characteristics are considered: current consumption, supply voltage, power consumption, size, temperature, price, and interface. Among the devices, AD8232ACPZ-R7 has the smallest size, and MAX30003CTI+ has the lowest power consumption. See appendix (Table 13).

Identified accelerometer sensors							
MPU 9255 AIS1120SXTR H3LIS331DLTR ADXL335BCPZ							
EVAL-ADXL335Z	101020051	MMA8452QR1	BMA400				

 Table 14– Identified accelerometer sensors.

For the 8 devices addressed in Table 14, the following characteristics are considered: current consumption, supply voltage, power consumption, size, temperature, price, interface, and range. Among the devices, BMA400 has both the smallest size and the lowest power consumption. See appendix (Table 14).

The selection criteria for above-mentioned hardware is based on considered characteristics in terms of *low energy consumption rates* (for extending the autonomy of the device battery as much as possible); *small-sized* (due to the usability requirement, the smaller the chip size the more adaptable the device form-factor can be); and *lower-cost* (in order to maintain an affordable price for the device's consumer targets).

4.4 Smartwatch and Smartphone Based Sensor Pack System

Wearable technologies such as smartphone and smartwatches are a fashion statement for some, a neat piece of technology for others. But for the PwD, they transcend any 'cool factor' and can be genuinely useful. For instance, they can provide medication reminders, track daily activity and even alert loved ones of any emergency. Smartphone and smartwatch present exciting opportunities for monitoring behaviour using widely available sensor data. This could support clinical research and practice aimed at improving quality of life among the growing number of PwD. However, it requires suitable tools for measuring behaviour in a natural real-life setting that can be easily implemented by others. Smartphones and smartwatches, as example of ATs that have considered hardware characteristics mentioned in section 4.2 (except the size and price), have high potential to help PwD for example in monitoring their location, tracking related wandering behaviours, and detecting accidental falls.

The functionality of smartphones and smartwatches can be developed by adding some supportive hardware (explained in part 4.1.1). For example, including accelerometers and gyroscopes can help identifying risky situations associated with falling or fainting. In such situations, they can send an alarm, notification, or message to the family members and/or caregiver for checking the situation, and if needed, to provide appropriate health support. This feature is implemented using a machine learning algorithm for fall detection that can analyse data resulting from the movements of a person in order to detect if a fall event has occurred or is occurring. The developed function help establishing an architecture that uses the smartwatch's sensors as input and performs a real-time assessment of risk.

In a case study, a Huawei 2 smartwatch is used for fall detection and location monitoring. For developing the smartwatch functions, the Gyroscope and Axial Accelerometers are used to detect fall, and GPS is used to evaluate the PwD's position and request help if wandering is occurred.

For analysing the collected data from the hardware, algorithms and neural networks is used. In the process of analyse, the position of PwD is verified against known routes and is then stored in a data base which may contain routes or geofences of places. In the case of geofences, a map with possible or forbidden positions must be previously established. In the case of routes, a buffer establishes the premises beyond the situations that the person is wandering. New routes can be also added.

5 CONCLUSIONS

This Deliverable focuses on identifying and documenting the necessary requirements (e.g. ATs, supportive services, and supportive hardware) to design appropriate wearable technologies (e.g. smartwatch and necklaces) for PwD in the CARELINK project. The designed devices can collect and configure the biological and environmental data and information from PwD's tracking, monitoring, pattern recognition algorithm, and their caregiver's alert. The output of this Deliverable, as a potential solution, will be then used in the implementation stage.

Therefore, this work reviews and addresses 86 potential ATs, 15 supportive services, and 75 supportive hardware. The results of this work provide an insight to the types and competitive capabilities and features of the commercially available technologies and services which can lead to some possible solutions to better deal with day–to–day realities of dementia.

The results show that the identified ATs and supportive services from the literature have each the potential to provide specific support for PwD in different circumstances. The identified hardware with **communication**, **localization and sensing capabilities** can give aid for designing and developing wearable technologies that **customized with low energy consumption**, **low-cost**, **and small-sized features** in response to the specific needs of PwD. Smartphone and smartwatch, as wearable technologies, are ideal for health care interventions, because they include multiple functions, such as Internet access, mobile telecommunication, sensors, notifications, and the ability to install applications that are clinically focused. Evidences show that smartphone and smartwatch are effective means for health and environment monitoring particularly for those suffering from dementia.

Having selected the suitable technologies and services for the purpose of this work and following the validation of the prototypes, the next step is realizing the user (PwD) needs and comfort. The focus is on reduction of the dimensions of the modules, adopting a format suitable for wearable integration, and the arrangement towards acceptance of the technologies. Taking it into account, the design of the specifications of a fully proprietary hardware solution is initiated in order to make sure the production of a device for the final user, after the conclusion of the CARELINK project, is useful. In the requirements process, tests and trials with endusers focus groups and early friendly user trials will be conducted to gather the requirements and feedback.

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7 APPENDIX

Appendix – Detailed Tables of State-of-the-Art Hardware

In this appendix, 8 tables are demonstrated, detailing the characteristics of the state-of-the-art hardware components, defined in section 4.1, namely SoC's for GNSS/GPS, Wi-Fi/Wireless, Bluetooth, GSM/LTE, heart rate, temperature, accelerometer and ECG sensors. The specific characteristics of the devices are detailed in section 4.2, and the analysis of the identified hardware are presented in section 4.3.



	GNSS/GPS										
						Characteristi	cs				
No	Products	Manufacturer	Current Consumption	Supply Voltage	Power Consumption	Size	Temperature	Price	Interface	Accuracy	Time to First Fix (TTFF)
1	Multi-GNSS Receiver Chip eRideOPUS	FURUNO Electric Co., Ltd.	Acquisition Mode: 61 mA (@ DC 3.3V)	1.8VDC / 3.3VDC	0.2013	7.0 x 7.0 mm	-40℃ to +85℃	N/A	UART, I2C, Forward /Reverse signal, Speed Pulse, Time Pulse, Clock	GPS: 2.5m (CEP) GPS + SBAS: 2.0m (CEP)	Hot Start: <1 sec Warm Start: 30 sec
	7M odel ePV 70 10 B	10	10	10		14	141		10	GPS+SBAS+ GLONASS: 2.0m (CEP)	Cold Start: 33 sec
	rences p://www.furuno.com/en/pi	[1]	[1]	[1]		[1]	[1]		[1]	[1]	[1]
	Multi-GNSS	FURUNO Electric	Acquisition Mode: 61	1.8VDC /	0.2013	110 x 112 x 30 mm	-40℃ to +85℃	N/A	UART, I2C, Forward	GPS: 2.5m (CEP)	Hot Start: <1 sec
2	Receiver Chip eRideOPUS 7Model ePV7000 B	Co., Ltd.	mA (@ DC 3.3V	3.3VDC					/Reverse signal, Speed Pulse, Time Pulse, Clock	GPS + SBAS: 2.0m (CEP) GPS + SBAS + GLONASS: 2.0m (CEP)	Warm Start: 30 sec Cold Start: 33 sec
Refe	rences	[1]	[1]	[1]		[1]	[1]		[1]	[1]	[1]
[1] http	o://www.furuno.com/en/pi	Maestro Wireless	41mA	3.3 V	0.1353	14 x 10.2 x 2.5 mm	-40℃ to +85℃	Qt 1:13,44 €	UART, SPI	< 2.5 m CEP	Hot Start2) < 1 sec
		Solutions	4 I IIIA	3.3 V	0.1555	14 X 10.2 X 2.5 mm	-40 C 10 +65 C	Qt 1.15,44 € Qt 25:13,44 €	UART, SPI	<2.5 mCEP (autonomous) <2.0 mCEP SBAS	
3	A2200-A							Qt 100: 10,68 €		<2.0 IIICEP 3BA3	Warm Start2) < 35 sec Cold Start2) < 35 sec
	rences	[1]	[2]	[2]		[2]	[3]	[2]	[2]	[3]	[3]
	://www.maestro-wireless ps://pt.mouser.com/Prod		reless-Solutions/A2200	-A?as=sGAEpiM	ZZM siLM B Iknimkt	YVBsaslotvaEY%25	2bXiYuHaE%3d				
[31 htt	ps://pt.mouser.com/datas								-	-	
	Flora Wearable	Adafruit	4mA ~ 20mA at 3.3V	3 to 4.3 V	0.066	15 x 15 x 4 mm	N/A	Qt 1: 32,76 €	N/A	< 3 meters	Hot start: 1 sec
4	Ultimate GPS Module 1059							(with adafruit board)			Warm start: 33 sec Cold start: 35 sec
Refe	rences	[1]	[4]	[2]		[2]		[2]	[2]	[3]	[4]
-	os://www.adafruit.com/							1			
[3] htt	ps://eu.mouser.com/Prod ps://www.adafruit.com/p ps://cdn-sbop.adafruit.co	roduct/10.59			52 bm4	qEwlqiNZOYgVbuD	SC5xOM EQ				
5	M TK3339	Adafruit	Acquisition: 19 mA	3.3V	0.0627	16 x 16 x 5 mm	-40℃ to +85℃	Qt 1:29,95€	UART(TTL)	< 3 meters	Hot start: 1 sec
5			Tracking: 16 mA		0.0528						Warm start: 33 sec
	(FGPM M OPA6H)		-								Cold start: 35 sec
Refe	rences	[1]	[2]	[1]		[1]	[2]	[1]	[2]	[1]	[3]
	ps://www.adafruit.com/pr ps://pt.aliexpress.com/ite					50 (700 54 4 http://			•	•	-
	ps://cdn-shop.adafruit.co					<u>35 iroz 344 inin.</u>					
6	Trimble Copernicus II	Diamond Point International	Consumption: (typ.) 44 mA (132 mW) @	+2.7 VDC to 3.3 VDC	0.132	19 x 19 x 2.54 mm	-40℃ to +85℃	N/A	28 surface-mount edge castellations 2 serial 3.0 V CM OS-compatible pulse once per second	Horizontal: <2.5 meters (50%). <5 meters (90%)	Cold start: 38 sec
Refe	rences	[1]	[1]	[1]		[1]	[1]		[2]	[1]	[2]
	://www.dpie.com/gps/er										
[2] htt 7	Venus638FLPx-L	Proto-PIC	Enhanced Acquisition:		0.22	10 x 10 x 1.3 mm	-40℃ to +85℃	Qt 1: 36.00 £	UART LVTTL level	2.5 m CEP	Hot start: 1 sec
	2 0 Hz		68 mA @ 3 3V Low Power		0.165						AGPS: 3.5 sec
			Acquisition: 50mA @								Cold start: 29 sec
Refe	rences	[1]	[2]	[2]		[1]	[2]	[1]	[2]	[2]	[2]
	os://www.proto-pic.co.uk	/gps-module-venus63	8flpx-I-20hz-14-channel		8						8
	ps://dlnmh9ip6v2uc.cloud	front.net/datasheets/ Tersus	Sensors/GPS/Venus638 (312 mA *calculated)	FLPx.pdf	1.56	92 x 54 x 13 mm	-40℃ to +85℃	Qt 1: \$999.00	N/A	Horizontal (RM S): 10	Warm Start: <30 sec
8	BX305	101000	(o iz mit ouloudica)	0,00	1.00		40 0 10 100 0	(BX305 GNSS RTK		mm+1ppm Vertical (RM S): 15 mm+1ppm	Cold Start: <50sec
Refe	rences	141	1.4	[2]		141	[4]	Board) (857.451€			
	os://www.tersus-anss.com	[1] n/product/bx305-oem	[1]	[2]		[1]	[1]	[3]		[1]	[2]
[2] htt	ps://www.tersus-gnss.com	m/assets/upload/file/2	20180731133334787.pdf	-							
<u>131 htt</u> 9	RXM-GPS-RM-B	Linx Technologies	Acquisition: 14mA	M in: 3V	0.0462	15 x 13 x 2.2 mm	-40℃ to +85℃	Qt1:16,51€	Serial	3 m	Hot Start: 30 sec
			Tracking: 12mA	Typ: 3.3V	0.396			Qt 25:13.82 €			Cold Start: 32 sec
			Standby: 0.135mA	Max: 4.3 V	0.004455						
Refe	rences	[1]	[2]	[2]		[2]	[2]	[2]	[2]	[2]	[3]
[1] http	os://linxtechnologies.com	/wp/_		0							
	ps://eu.mouser.com/Prod ps://eu.mouser.com/datas					EBA POVINICUIV e5n/	atuweszpą%252bl	NGOEKNG%80%80			
10	7DLTS0075	Japan Radio Co., Ltd	Icc: 42mA typ. (DC3.3V. +25℃.	DC3.3V	0.1386	6 × 6 × 1.2 mm	-40℃ to +85℃	N/A	N/A	2.2 m CEP	Hot Start: 2 sec
											Warm Start: 8 sec
											Cold Start: 35 sec
	rences c://www.jrc.co.jp/eng/pro	[1] duct/lineup/7dlts0075	[1]	[1]		[1]	[1]			[1]	[1]
11	UBX-M8230-CT	u-blox	36 mA @ 1.4 V	1.4 V to 3.6 V	0.054	2.99 x 3.21 x 0.36	-40℃ to +85℃	N/A	ART USB SPI DDC (I2C	3.5 m CEP	Hot Start: 1 sec
						mm			compliant)		Aided Start: 2 sec
											Cold Start: 26 sec
	rences	[1]	[2]	[2]		[1]	[1]		[2]	[2]	[2]
	ps://www.u-blox.com/en/r			mary %28UBX-16	017340%29.pdf						

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Table 8. Proposed Wi-Fi / Wireless devices and characteristics details.

					Wi-Fi / V Charact					
No	Products	Manufacturer	Current Consumption	Supply Voltage	Power Consumption	Size	Temperature	Price	Interface	Protocol
1	MOD-WIFI- ESP8266	Olimex Ltd.	80 mA	3.3 V	0.264	5 x 5 mm	0℃ to +70℃	Qt 1: 5,45€	I2C, SDIO 2.0, SPI, UART	802.11b/g/n
Refe	rences	[1]	[3]	[3]		[3]	[2]	[2]	[2]	[3]
-	os://www.olimex.c		[0]	[0]		101	[-]	[-]	1-1	[0]
						8E8Cjr8THuSBIwx5fc	12tykGKhxvg%3d			
[<u>3] htt</u> 2	ps://eu.mouser.co	m/datasheet/2/306/ Espressif Systems		2.7 V to 3.6 V	95238.pdf 0.288	5 x 5 mm	-40℃ to +125℃	Qt 1: 1,48 €	ADC, GPIO, I2C, I2S,	802.11b/g/n/e/i
	ESP8285								PWM, SDIO, SPI, UART	-
	rences	[1]	[3]	[2]		[3]	[2]	[2]	[2]	[2]
	ps://www.espressi		propoit Systems/ES		xNavsvn49Ad%252t					
-		if.com/sites/default/				<u>, , , , , , , , , , , , , , , , , , , </u>				
3	ESP8266EX	Espressif Systems	80 mA	2.5 V to 3.6 V	0.288	5 x 5 mm	-40℃ to +125℃	Qt 1: 1,31€	UART/SDIO/SPI/I2C	802.11b/g/n/e/i
	rences	[1]	[3]	[2]		[2]	[2]	[2]	[2]	[3]
	ps://www.espressi		oressif-Systems/ES	P8266EX?as=s0	GAEpiMZZM ve4%2f	bfQkoi%252bGif8WC	prhV4nak1mHM9X	is%3d_		
		m/datasheet/2/891/								
4	CleO35- WiFi1	Bridgetek	80 mA	3.3 V	0.264	35.3 x 31.6 x 4.6 mm	-40℃ to +85℃	Qt 1: 18,66€	UART	802.11b mode
Refe	rences	[1]	[3]	[2]		[2]	[2]	[2]	[2]	[3]
-	o://brtchip.com/_									
			-		ZZM ve4%2fbfQkoj9	252bIZJxVbenzFUH	x%2f9QS0EUx4%30	±		
[<u>3] htt</u> 5	ps://eu.mouser.co	m/datasheet/2/880/ Realtek	DS CleO35 WIFI- 80 mA	3.0~3.6 V	0.288	24 x 16x 0.8 mm	-20℃ to +125℃	Qt 1: \$3.99	HSPI, UART, I2C,	802.11b modle
5	RTL8710	~ · · ·							I2S, IR Remote Control, PWM, GPIO	
-	rences	[3]	[1]	[1]		[1]	[1]	[2]	[1]	[1]
		a.ne.ip/aitendo_data udio.com/RTL8710-			0/R1L8/10%20wift%	20module%20specific	ation.pdf_			
[3] htt	p://www.realtek.co	om.tw/products/pro	ductsView.aspx?L	angid=1&PNid=33	&PFid=45&Level=4&	Conn=3&ProdID=361				
0										
6	88M W302	Marvell	4.5 mA	3.3 V	0.01485	8 x 8 mm	-40℃ to +85℃	N/A	SSP/SPI/I2S, UART,	802.11n/g/b
Refe	rences	[1]	4.5 mA [2]	3.3 V [2]	0.01485	8 x 8 mm [2]	-40°C to +85°C [2]	N/A	SSP/SPI/I2S, UART, [2]	802.11n/g/b [2]
Refe	rences p://www.marvell.co	[1]	[2]	[2]	0.01485			N/A		-
Refe	rences p://www.marvell.co	[1] 2m/_	[2]	[2]	0.01485 N/A			N/A N/A		-
Refer [1] htt [2] htt 7 Refer	rences p://www.marvell.co ps://www.marvell. wE935B00 rences	[1] com/microcontroller Wi2Wi [1]	[2] s/assets/M.V-S109 N/A	[2] 9 <u>36-01C.pdf</u> 3.3V [1]	N/A	[2]	[2]	-	[2]	[2]
Refer [1] htt [2] htt 7 Refer	rences p://www.marvell.co ps://www.marvell.co wE935B00 rences p://www.wi2wi.com	[1] com/_ wi2wi	[2] s/assets/M.V-S109 N/A	[2] 9 <u>36-01C.pdf</u> 3.3V [1]	N/A	[2] 15 x 16.5 x 1.86 mm	[2] -40℃ to +85℃	-	[2] UART, SPI & USB*	[2]
R ef en [1] http [2] htt 7 R ef en [1] http	rences p://www.marvell.co ps://www.marvell. wE935B00 rences	[1] com/microcontroller Wi2Wi [1] m/wireless-connectiv	[2] s/assets/M.V-S109 N/A ity/embedded-seri	[2] <u>936-01C.pdf</u> 3.3V [1] es/wi-fi/we935b0	N/A	[2] 15 x 16.5 x 1.86 mm [1]	[2] -40°C to +85°C [1]	N/A	[2] UART, SPI & USB* [1]	[2] IEEE [1]
Refer [1] http: [2] http: [2] http: Refer Refer	rences p://www.marvell.co ps://www.marvell.co wE935B00 rences p://www.wi2wi.com ST60-SIPT- C rences	[1] pm/. com/microcontroller Wi2Wi [1] m/wireless-connectiv Laird [1]	[2] N/A itty/embedded-seri 620 mA *M aximum	[2] <u>936-01C.pdf</u> 3.3V [1] es/wi-fi/we935b0	N/A	[2] 15 x 16.5 x 1.86 mm [1]	[2] -40°C to +85°C [1]	N/A	[2] UART, SPI & USB* [1] PCIe 3.0, SDIO,	[2] IEEE [1]
R ef ei [1] htti [2] htti 7 R ef ei [1] htti 8 R ef ei [1] htti	rences p://www.marvell.co p://www.marvell.co wE935B00 rences p://www.wi2wi.com ST60-SIPT- C rences p://www.lairdtech	[1] pm/_ com/microcontroller Wi2WI [1] m/wireless-connectiv Laird [1] .com/_	[2] N/A N/A //ty/embedded-seri 620 mA *Maximum Current [3]	[2] 936-01C.pdf 3.3V [1] es/wi-fl/we935b0 3.3 V [2]	N/A 0 2.046	[2] 15 x 16.5 x 1.86 mm [1] 13 x 14 x 1.87 mm [3]	[2] -40°C to +85°C [1] -30°C to +85°C [2]	N/A Qt 1: 23,41€ [2]	[2] UART, SPI & USB* [1] PCIe 3.0, SDIO, UART, USB2.0	[2] IEEE [1] 802.11a/b/g/n/a
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R efei [1] http://www.sefection.com/ R efei [1] http://www.sefection.com/ [2] http://wwww.sefection.com/ [2] http://www.sefection.com/ [2] http://www.sefection.com/ [2] http://www.sefection.com/ [2] http://www.sefection.com/ [2] http://wwwwwwwwwwwwwwwwwwwwwwwwwwwwwwwwww	rences	[1] m/. com/microcontroller Wi2Wi [1] m/wireless-connectiv Laird [1] .com/_ m/ProductDetail/Lai m/ProductDetail/Lai m/Araasheet/2/223/ Qualcomm [4] wiki/Atheros_AR93 pom/index.php/news: 2ks.com/ubloadspro comm.com/ Texas Instruments [1] m/ProductDetail/Te (ds/symlink/cc3100)	[2] s/assets/M V-S109 N/A fity/embedded-seri fd20 mA *Maximum Current [3] rd/ST60-SIPT-C2c Datasheet - 60-S 373mA (@3.3V)* *Max. [3] 31 /openwrt-ar9331-ca ductos/ar9331-da 53 mA [2] xas-Instruments/C(pdf	[2] 936-01C.pdf 3.3V [1] es/wi-fi/we935b0 3.3 V [2] 12 to 3.3 VDC [2] 12 to 3.3 VDC [2] 12 to 3.3 VDC [2] 12 to 3.4 VDC [2] 12 to 3.6 V [2] 2.1V to 3.6 V	N/A Q. 2.046 iJVLpW1FR2z%2fxU. 1.2309 d/#.WypmB9JKiJB. 0.1908 0.1908	[2] 15 x 16.5 x 1.86 mm [1] 13 x 14 x 1.87 mm [3] 8H3gaof0zuM F8J%2f 12 x 12 mm [1] 1x 9.15 x 9.15 mm [2] vxVoyCXc2K7IP6tC>	[2] -40°C to +85°C [1] -30°C to +85°C [2] vsuO3uv9tnyELUw 0 to 110 °C [1] -40°C to +85°C [2] (lusP8K4wPDJQSN	N/A Qt 1: 23,41€ [2] %3d%3d N/A Qt 1: 6,17€ Qt 25:5,16 € Qt 100: 4,62 € [2] 1kg%3d	[2] UART, SPI & USB* [1] PCIe 3.0, SDIO, UART, USB2.0 [2] JTAG, UART, GPIO, [2\$/S-PDIF, SLIC (VoIP/PCM) 2 x [1], [2] SPI, UART [2]	[2] IEEE [1] 802.11a/b/g/n/a [2] 802.11b/g/n [3] 802.11b/g/n [3]
Refei [1] http: [2] http: Refei [1] http: [3] http: [rences D://www.marvell.co ps://www.marvell.co ps://www.wi2wi.com ST60-SIPT- C rences ps://www.lairdteet ps://eu.mouser.co ps://eu.mouser.co ps://www.ezsbc.co ps://www.ezsbc.c	[1] m/. com/microcontroller Wi2Wi [1] m/wireless-connectiv Laird [1] .com/_ m/ProductDetail/Lai m/ProductDetail/Lai m/Araasheet/2/223/ Qualcomm [4] wiki/Atheros_AR93 pom/index.php/news: 2ks.com/ubloadspro comm.com/ Texas Instruments [1] m/ProductDetail/Te (ds/symlink/cc3100)	[2] s/assets/M V-S109 N/A fity/embedded-seri fd20 mA *Maximum Current [3] rd/ST60-SIPT-C2c Datasheet - 60-S 373mA (@3.3V)* *Max. [3] 31 /openwrt-ar9331-ca ductos/ar9331-da 53 mA [2] xas-Instruments/C(pdf	[2] 936-01C.pdf 3.3V [1] es/wi-fi/we935b0 3.3 V [2] 12 to 3.3 VDC [2] 12 to 3.3 VDC [2] 12 to 3.3 VDC [2] 12 to 3.4 VDC [2] 12 to 3.6 V [2] 2.1V to 3.6 V	N/A Q. 2.046 iJVLpW1FR2z%2fxU. 1.2309 d/#.WypmB9JKiJB. 0.1908 0.1908	[2] 15 x 16.5 x 1.86 mm [1] 13 x 14 x 1.87 mm [3] 8H3gaof0zuM F8J%2f 12 x 12 mm [1] 1x 9.15 x 9.15 mm [2] vxVoyCXc2K7IP6tC>	[2] -40°C to +85°C [1] -30°C to +85°C [2] vsuO3uv9tnyELUw 0 to 110 °C [1] -40°C to +85°C [2] (lusP8K4wPDJQSN	N/A Qt 1: 23,41€ [2] %2d%3d N/A Qt 1: 6,17 € Qt 25:5,16 € Qt 100: 4,62 € [2] Kg%3d Qt 1: 10,59 € Qt 25:9,23 €	[2] UART, SPI & USB* [1] PCIe 3.0, SDIO, UART, USB2.0 [2] JTAG, UART, GPIO, [2\$/S-PDIF, SLIC (VoIP/PCM) 2 x [1], [2] SPI, UART [2]	[2] IEEE [1] 802.11a/b/g/n/a [2] 802.11b/g/n [3] 802.11b/g/n [3]
R ef ei [1] htti [2] htti R ef ei [1] htti 8 R ef ei [1] htti [2] htti [2] htti [2] htti [3] htti [4] htti [4] htti [4] htti [3] htti [4]	rences c://www.marvell.cc ps://www.marvell.c WE935B00 rences c://www.wi2wi.com ST60-SIPT- C rences ps://www.lairditect ps://eu.mouser.co ps://www.ezsbc.cc p	[1] m/. com/micro.controller Wi2Wi [1] m/wireless-connectiv Laird [1] com/_ m/ProductDetail/Lai m/datasheet/2/223// Qualcomm [4] wiki/Atheros_AR93 om/index.php/news: cks.com/uploadspro com.com/ Texas Instruments [1] m/ProductDetail/Tei (ds/symlink/co3100) Texas Instruments [1]	[2] s/assets/M V-S109 N/A dty/embedded-seri f620 mA *Maximum Current [3] rd/ST60-SIPT-C?cc Datasheet - 60-S 373mA (@3.3V)* *Max. [3] 31 /openwrt-ar9331-da 53 mA [2] xas-Instruments/Co odf 54 mA [3]	[2] 936-01C.pdf 3.3V [1] es/wi-fi/we935b0 3.3 V [2] 1.2 to 3.3 VDC [2] 1.2 to 3.3 VDC [2] 1.2 to 3.3 VDC [2] 2.1V to 3.6 V [2] 2.3 Voc 3.6 V [2] 2.3 V to 3.6 V [2]	N/A 0. 2.046 2.046 1.209 1.2309 d/# WypmB9JKiJB 0.1908 0.1908 0.1944	[2] 15 x 16.5 x 1.86 mm [1] 13 x 14 x 1.87 mm [3] 8H3gaof0zuM F8J92f 12 x 12 mm [1] 1 x 9.15 x 9.15 mm [2] vxV oyCX c2K7[P6IC> 1.27x20.5 x17.5-mm	[2] -40°C to +85°C [1] -30°C to +85°C [2] vsuO3uv9tnyELUw 0 to 110 °C [1] -40°C to +85°C [2] ClusP8K4wPDJQSA -20°C to +70°C [2]	N/A Qt 1: 23,41 \in [2] %3d%3d N/A Qt 1: 6,17 \in Qt 25:5,16 \in Qt 100: 4,62 \in [2] Akg%3d Qt 1: 10,59 \in Qt 25:9,23 \in Qt 100: 8,22 \in [2]	[2] UART, SPI & USB* [1] PCIe 3.0, SDIO, UART, USB2.0 [2] JTAG, UART, GPIO, [25/S-PDIF, SLIC (VoIP/PCM) 2 x [1], [2] SPI, UART [2] SPI [3]	[2] IEEE [1] 802.11a/b/g/n/a [2] 802.11b/g/n [3] 802.11b/g/n [3] 802.11b/g/n

Table 9. Proposed Bluetooth devices and characteristics details.

	Bluetooth										
				Char	acteristics						
No	Products	Manufacturer	Current Consumption	Supply Voltage	Power Consumption	Size	Temperature	Price	Interface	Protocol	
1	RN4020- V/RMBEC133	Microchip Technology	16 mA	1.8 V to 3.6 V	0.0576	11.5 x 19.5 x 2.5 mm	-30℃ to +85℃	Qt 1: 8,69 € Qt 10:7.97 €	I2C, UART	Bluetooth 4.1	
Refer	ences	[1]	[3]	[2]	ł	[2]	[2]	Qt 25: 7,02 € [2]	[2]	[2]	
[1] http	s://www.microchip.co	om/	•								
	os://eu.mouser.com/Pr		ip-Technology/RN4020-V-RMBF 2279B-846406.pdf	EC1332qs=sGAEr	oiM77Mve4%2fbfQ	koj%252bP9drDq8Y	7PD813vXG6U%2f	ns%3d_			
2	ATBTLC1000A- MU-Y	Microchip Technology/Atmel	3.0 mA peak TX current (0dBm,	1.8 V to 4.3 V	0.0108	4 x 4 mm	-40℃ to +85℃	Qt 1: 3,81€ Qt 25:3,06 € Qt 100: 2,79 €	SPI, UART	Bluetooth V4.1	
Refer	ences	[1]	[3]	[2]		[2]	[2]	[2]	[2]	[3]	
	://www.microchip.con										
			ip-Technology-Atmel/ATBTLC100 I-42409-ATBTLC1000-QFN-SoC			ubTlf5ZDrkWU%25	2bYChlpK3n%2fkr7	<u>10%3d_</u>			
3	M KW 3 0 Z 16 0 V HM 4	NXP / Freescale	6.5 mA (DCDC in buck mode, 3.6 V supply)	3.6 V	0.0234	5 x5 x1 mm	-40℃ to +85℃	Qt 1: 2,74 € Qt 25:2,22 € Qt 100: 2,05 €	I2C, SPI, UART	Bluetooth 4.1	
Refer		[1]	[3]	[2]		[3]	[2]	[2]	[2]	[3]	
	s://www.nxp.com/_	roduct Detail/NX P-Fre	eescale/MKW30Z160VHM4?gs=d		rgi8bbzgw%3D%3F						
			/40Z160-1127201pdf		<u>515166123W7860785</u>	<u> </u>					
4	CC2560BYFV R	Texas Instruments	1 mA	2.2 V to 4.8 V	0.0036	8.0 mm × 8.0 mm × 0.6 mm	-40℃ to +85℃	Qt 1: 3,92 € Qt 10:2,53 € Qt 100: 2,89 €	128	Bluetooth 4.1	
Refer		[1]	[3]	[2]		[3]	[2]	[2]	[2]	[3]	
	://www.ti.com/	roduct Dotail/Toyac In	struments/CC2560BYFVR?as=st	GA EpiM ZZM vove			%ad				
	://www.ti.com/lit/ds/		Struments/CC2500BTT VIC: US=5	<u>OALDIWIZZIVI VZV</u>	<u>, LACJZINOSTIBED</u>		<u>7890</u>				
5	CC2640R2FR GZT	Texas Instruments	1.45 mA + 31 µA/M Hz	1.8 V to 3.8 V	0.00435	4 × 4 mm	-40℃ to +85℃	Qt 1: 4,58 € Qt 10:4,11 € Qt 100: 3,37 €	I2C, I2S, SSI, UART	Bluetooth 4.2/5	
Refer		[1]	[3]	[2]		[3	[2]	[2]	[2]	[3]	
	://www.ti.com/	roductDetail/Texas-In	struments/CC2640R2FRGZT?as	GA EpiM ZZM u	tXGli8Av4kMxm20	n7fW/7lOa5xib.nKcv4s	8d				
	://www.ti.com/lit/ds/										
6	CC2564BRVM R	Texas Instruments	1 mA	2.2 V to 4.8 V	0.0036	8 x 8 mm	-40℃ to +85℃	Qt 1: 4,09 € Qt 10:3,68 € Qt 100: 3,02 €	UART PCM-I2S	Bluetooth v4.1 (BLE) + EDR	
Refer		[1]	[3]	[2]		[3]	[2]	[2]	[2].[3]	[4]	
	://www.ti.com/ ps://eu.mouser.com/Pi	roductDetail/Texas-In	struments/CC2564BRV/MR2qs=	sGA EpiM ZZM vcF	RsgoM EfeP89Kk1Y1	3KKSpdBXG9W0d9	@52bE%8d				
	://www.ti.com/lit/ds/										
[4] http	s://www.arrow.com/e	Nordic	0.3 mA no RAM retention	1.7 V to 3.6 V	0.00108	6 x 6 x.85 mm	-40℃ to +85℃	Qt 1:3,06 €	2-Wire, SPI,	Bluetooth	
7	nRF52810- QFAA-R	Semiconductor	1.4 mA All peripherals in IDLE 1.8 µA All peripherals in IDLE 40 nA per 4kB RAM retention		0.00504 0.00000648 0.000000144		-40 0 10 4850	Qt 10:2,46 € Qt 100:2,24 €	UART	5/ANT/2.4GHz proprietary	
Refer	ences	[1]	[3]	[2]		[3]	[2	[2]	[2]	[3]	
	://www.nordicsemi.co		Semiconductor/nRF52810-QFAA-								
	://infocenter.pordicse			R / US=SGAEDIWIZ	ZIM URBOCZOBDI TA	CHATJDN4OCWChse	BST 0008BdHVtB.	2XIIW7@07@0			
8	nRF8001- R2Q32-T	Nordic Semiconductor	11 mA Active TX peak current at 12.5 mA Active RX peak current	1.9 V to 3.6 V	0.0396 0.045	5 x 5 mm	-40℃ to +85℃	Qt 1: 3,49 € Qt 10:2,80 € Qt 100: 2,55 €	PC, SPI, UART	Bluetooth v4.0	
Refer		[1]	[3]	[2]		3]	[2]	[2]	[4]	[4]	
	://www.nordicsemi.co		Semiconductor/nRF8001-R2Q32-	T?gs=%2fha2pvF	aduhJLVpg4RFNFh	IHh2i8dxvYAITsOr8	50 lhkxKR kanc4 SQ	/ad%ad			
[3] http	s://www.nordicsemi.o	com/eng/content/dow	nload/2981/38488/file/nRE8001	PS_v13.pdf							
[4] http	s://www.diaikev.pt/p	Nordic	dic-semiconductor-asa/NRF8001-	R2Q32-T/1490-10	026-ND/4626390	6 x 6 mm	-40°C to +85°C	Qt 1:4 37€	2 Wire I2C	Support for	
9	nRF52832- QFAB-R	Semiconductor	0.7 μA at 3 V in OFF mode with 1.9 μA at 3 V in ON mode, no		0.0000021 0.0000057			Qt 10:3,51€ Qt 100:3,20€	I2S, PDM, PPI, SPI, UART	concurrent multi-protocol	
Refer	ences ://www.nordicsemi.co	[1]	[3]	[2]	1	[3]	[2]	[2]	[2]	[3]	
<u>[21 http</u>	s://eu.mouser.com/P	roductDetail/Nordic-S	Semiconductor/nRF52832-QFAB-	-R?qs=sGAEpiM2	ZZM uKfY siLTlamFe	ogZzM9xEMAZBdN	aGWL9g%3d				
<u>[3] http</u> 10	BLUENRG-132		2832_PS_v13-1117956 pdf_ 8.3 mA TX current (@ -2 dBm, 3.0 V)	1.7 V to 3.6 V	0.0249	5 x 5 mm	-40℃ to +105℃	Qt 1: 3,26 € Qt 10:2,77 €	I2C, SPI, UART	N/A	
Refer	ences	[1]	[3]	[2]		[2]	[2]	Qt 100:2,40 € [2]	[2]		
[1] http	s://www.st.com/	13	[-]	[-]			1-1		[-]		
	s://eu.mouser.com/Pr		electronics/BLUENRG-132?as=s	GAEpiMZZM u3x	u3GWivQiPxHf6%25	2b6mhpnSi4T1hsVo	Ks%3d_				
		Skylab	TX Peak @4dBm 7.5mA*	1.7 V~3.6V	0.0225	17.4 × 13.7 × 1.9 mm	-40℃ to +85℃	N/A	SPI, I2C,	Bluetooth 4.2	
11	SKB369A		RX Peak 5.4 mA* Sleep Mode (avg.) 0.4 uA* Idle Mode (avg.) 1.2 uA*		0.0162 0.0000012 0.0000036				UART (CTS/RTS), CPU		
Refer	ences	[1]	*Current(peak) @3V [2]	[2]	<u> </u>	[2]	[2]		[3]	[3]	
[1] http	://www.skylabmodule	.com/			.	[4]	[4]	l	[3]	[5]	
			loads/SkyLab_SKB369_V107_da	atasheet.pdf.							
131 http	www.skvlabmodule	Insight SiP	Peak current, Rx active 5.4 mA	1.7 V to 5.5 V	0.0297	8.0 x 8.0 x 1.0 mm	-40℃ to +85℃ C	N/A	USB, SPI,	BLE & ANT	
12	BLE (ISP1807)		Peak current, Tx @0dBm 4.9 Peak current, Tx @+8dBm 14.1 Deep sleep current 0.4 µA		0.02695 0.07755 0.0000022				UART, PDM, I2C	protocol	
Refer	ences	[1]	[1]	[1]		[1]	[1]		[1]	[1]	
[1] bttp	automa incidenta in an	m/n roducto/bluetoct	b-smart-modules/isp.1807								



Table 10. Proposed GSM/LTE devices and characteristics details.

					GSM/LTE					
					Characteristic	s				
			T		1		1		1	1
No	Products	Manufacturer	Current Consumption	Supply Voltage	Power Consumption	Size	Temperature	Price	Interface	Protocol
1		Pycom	Idle (no radios) 62.7	3.3 V – 5.5 V	0.3135	55 x 20 x 3.5 mm	N/A	Qt 1: 54.00 €	UART, SPI, I2C,	LTE-CAT M 1/N
	510		mA @5V Deep Sleep 24mA @5V		0.12	(board)			micro SD card	LoRa and Sigfo
	FiPy		LTE Tx 173 mA @5V		0.865					
			LTE Rx 74.5 mA @5V		0.3725					
efere	ences	[1]	[2]	[1]		[1]		[1]	[1]	[2]
	s://pvcom.io/product/fip		[2]	1.1		1.1		1.1	19	[2]
	s://docs.pvcom.io/chapt		s/finv-specsheet.pdf							
2	Adafruit Feather	Adafruit	N/F	3.3 V	N/A	61 x 23 x 7 mm	N/A	Qt 1: \$44.95	I2C, SPI, USB	GSM
2	32u4 FONA					(board)		-38.56 €		GPRS
e for		[4]	10	14	1	, ,			14	
	ences	[1]	[1]	[1]	<u> </u>	[1]		[1]	[1]	[1]
	s://www.adafruit.com/pr		Device Off Manda C5	2.0.1/ 42.1/DC	0 00000505	0.0 40 0	1000 4- 105 90	01 4 6 00 05		
3		U-blox	Power Off Mode 65 µA	3.9 V-12 VDC	0.00002535	26 x 16 x 3 mm	-40℃ to +85℃	Qt 1: \$69.95	UART, SPI, I2S,	UM TS/HSPA
	Particle Electron		Idle Mode 0.5mA		0.00195			(60 €) *Dev. Kit #1	USB 2.0	
			HSDPA Connected Mode (Tx / Rx call		2.652			Qt 1: \$138.50	GPIO	
			enabled) 680mA					(118,80 € *Dev. Kit	 	ļ
	ences	[1]	[2]	[2]		[2]	[2]	[2]	[2]	[2]
<u>1] http:</u>	s://www.u-blox.com/en/p	oroduct/sara-u2-series								
2] http	s://www.u-blox.com/site	s/default/files/SARA-U	2 DataSheet %28UBX-1	3005287%29.pdf	-					
1 http:	s://docs.particle.io/datas	sheets/electron-(cellular).	/electron-datasheet/							
1 http:	s://www.sparkfun.com/p	roducts/14212								
	s://core-electronics.com									
	s://hologram.io/docs/ref									
	s//nologram.io/docs/rei	SIM Com Wireless	Power off: 7 uA	3.0 V~4.3 V	0.0000301	24 X 24 X 2.6	-40℃ to +85℃	Qt 1:\$38.20	UART, I2C, GPIO,	GSM, GPRS
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			Sleep:1mA		0.0043					
			Idle: 11 mA		0.0473					
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1] http: 5 6 9 9 1] http: 6 1] http: 7 7 9 9 9 1] http: 1] http: 1] http: 2] http: 2] http: 2] http: 2] http: 2] http: 3] http: 3] http: 3] http: 4] http: 6 9 9 9 9 9 9 9 9 9 9 9 9 9 9 9 9 9 9	<pre>//sincomm2m.com/En/m /s://techship.com/produc Hologram Dash ences s://core-electronics.com /s://bologramio/docs/ref SIM 900 Quad Band GSM GPRS shield ences s://www.ptrobotics.com //wiki.epalsite.com/inde//wiki.epalsite.com/inde//wiki.epalsite.c</pre>	ts/simcom-sim7000e-ca Core Electronics [1] au/hologram-dash.html ierence/dash/datasheet/ PTROBOTICS [1] [1] (com/5711-sim900-quad Seeed Studio [1] m/ cct Detail/Seeed-Studio/ seeed studio/seeed-linkit-one/e pos/102030002-776038	s t-m-nb-iot-smt/_ 3.32 V / 250 mA [2] Sleep Mode: 1.5 mA Voice Call: 250 mA GPRS Data Mode: 440 [2] ad-Band_GPRS_shield 1mA [5] 102030002?qs=SEIPoaY cone/ n_ .pdf_	3.3 V [2] 5 V - 26 V [3] 3.3 V [3] 2 y5 J5 / JmtKoe / f	0.83 0.0075 125 2.2 d.html 0.0033	55 x 20 x 9 mm (board) [2] 85 x 55 x 15 mm (board) [3] 83.92 x 53.34 [3]	-40°C to +85°C -40°C to +85°C [2]	Qt t \$ 138.50 [1] Qt t 55,35 € [2] Qt t 48,38 € [2]	I2C, SPI, UART, CAN, analog [1] UART [3] Analog I/O, PWM, I2C, SPI, UART [3]	2G: GPRS / ED 3G: UMTS / HS [1] GSM, GPRS [3] [3] [4].[5]



Table 11. Proposed heart rate devices and characteristics details.

	Heart Rate											
	-	-	•	Characte	eristics	•						
No	Products	Manufacturer	Current Consumption	Supply Voltage	Power Consumption	Size	Temperature	Price	Interface			
1	BH1790GLC-E2	ROHM Semiconductor	Typ: 200 uA	1.7 V to 3.6 V	0.00072	2.80 x 2.80 x 1.00	-20℃ to +85℃	Qt 1: 5,47 € Qt 25:4,72 € Qt 100: 4,09 €	12C			
Refe	rences	[1]	[2]	[3]		[4]	[3]	[2]	[3]			
	ps://www.rohm.com/											
	tps://eu.mouser.com/ProductDe			<u>is=%2fha2pyFadu</u>	hskeYDgkK042%2fT	<u>kHTXfYdN3ir8ROMJ</u>	iO1zY4pXds45pA%	<u>3d%3d</u>				
[S] III	ps.//eu.nouser.com/datasneet/	Analog Devices	170 uA	2 V to 3.5 V	0.000595	4 × 4 mm	-40℃ to +85℃	Qt 1:2,81€	N/A			
2	AD8232ACPZ-R7							Qt 25:2,26 € Qt 100: 2,06 €				
Refe	rences	[1]	[2]	[2]		[2]	[2	[2]				
	p://www.analog.com/en/index.h											
[2] htt	tps://eu.mouser.com/ProductDe	etail/Analog-Devices/AI Microchip	8 uA @ 31kHz, 1.8V	GA EpiM ZZM v9Q 2.3 V to 5.5 V	1JIOM o%2ftTwzkje34 0.0000144	5 x 5 x 0.5 mm	-40℃ to +85℃	Qt 1:2,97€	I2C, SPI,			
3	PIC 16 F 1779 - E/PT	Technology	32 uA/MHz @ 1.8V	2.3 V 10 5.5 V	0.0000576	5 X 5 X 0.5 mm	-400104050	Qt 25:2,40 € Qt 100: 2,17 €	USART			
	rences	[1]	[3]	[2]		[3]	[2]	[2]	[2]			
	ps://www.microchip.com/_											
	ps://eu.mouser.com/ProductDe		0,	/qs=%2fha2pyEac	lugaEp1sk%2fICGex4	IO7BOU1nmtnlk2SgpF	-qqHsqHVvRFBO%	<u>3d%3d_</u>				
4	ATSAMB11-ZR210CA- ND	Microchip Technology/Atmel	Receiving: 5 mA Transmitting: 2.3 mA	1.8 V ~4.3 V	0.0215 0.00989	5.50 x 4.50 mm	-40℃~85℃	Qt 1: \$ 7,25 Qt 25: \$ 6,63	I2C, SPI, UART			
Refe	rences	[1]	[2]	[2]		[3]	[2]	[2]	[2]			
[1] http	p://www.microchip.com/											
[2] ht	tps://www.digikey.lv/product-o	detail/en/microchip-tech	nology/ATSAMB11-ZF	210CA/ATSAME	311-ZR210CA-ND/614	<u>48940</u>						
[3] htt	p://ww1.microchip.com/downlo						4000 1 0.500	0140000	N/A			
5	SFH 7070	OSRAM Opto Semiconductors	25 mA	3.0 V	0.075	7.5 x 3.9 x 0.9 mm	-40℃ to +85℃	Qt 1: 3,00 € Qt 25: 1,98 € Qt 100: 1,72 €	IV/A			
Refe	rences	[1]	[3]	[3]		[3]	[3]	[2]				
	ps://www.osram.com/os/?_ tps://eu.mouser.com/ProductDe			0			N/0/0-1					
	bs://media.osram.info/media/re				addireidin/qysidKoke	2RUUKUS8ONG8IGA	1 700					
6	SFH 7051	OSRAM Opto Semiconductors	N/F	5 V	N/A	4.7 x 2.5 x 0.9 mm	-40℃ to +85℃	Qt 1: 2,07 € Qt 25:1,37 € Qt 100: 1,19 €	N/A			
Refe	rences	[1]		[3]		[3]	[2]	[2]				
	ps://www.osram.com/os/?											
	tps://eu.mouser.com/ProductDe				duioHwteQmnfD8%25	2bsIAMIRokoFuTfkr	cdVCI%3d_					
[3] htt	tps://media.osram.info/media/re	Silicon Labs	4.3 mA	1.8 V	0.00774	4.9 x 2.85 x1.2 mm	-40℃ to +85℃	Qt 1: 3,75€	I2C			
7	SI1143-M01-GMR			-				Qt 25:3,46 € Qt 100: 3,09 €				
	rences	[2]	[2]	[2]		[3]	[2]	[2]	[3]			
	<u>ps://www.silabs.com/_</u> ps://eu.mouser.com/ProductDe	atail/Silicon Laba/Sidda			Xiw%2D%2D							
	tps://eu.mouser.com/datasheet/			<u>5gSelimAtt pevlk</u>	<u>XIW7@D7@D_</u>							
		Texas Instruments	N/F	2 V to 3.6 V	N/A	3.07×3.07×0.5	-20℃ to +70℃	Qt 1:6,42 €	Serial, SPI			
8	AFE4403YZPT					mm		Qt25:5,37€ Qt100:4,81€				
	References [1] [2] [3] [2] [2] [2]											
	<u>p://www.ti.com/_</u> :ps://eu.mouser.com/ProductDe	etail/Texas-Instruments/			idbTccA64wP3P7P	H1hTH0SuvEEM 618/2	1					
-	tps://eu.mouser.com/ProductDe		AT 2440312PT (QS=S0		MUDICCA04WDZRZD		<u> </u>					
	SparkFun Particle	Makerlab Electronics	Typ. 0.6 mA	3.3 V	0.00198	5.6 x 3.3 x 1.5 5 mm	-40℃ to +85℃	Qt 1: 14,65€	I2C			
9	Sensor Breakout – MAX30105		M ax. 1.1 mA		0.00363							
	rences	[1]	[2]	[1]		[2]	[2]	[3]	[1]			
	ps://www.makerlab-electronics		•	ut-max30105/								
	Pttps://cdn.sparkfun.com/assets/learn_tutorials/5/7/7/MAX30105_3.pdf. Pttps://www.exp-tech.de/sensoren/biometrisch/7880/sparkfun-particle-sensor-breakout-max30105											

Table 12. Proposed temperature devices and characteristics details.

	Temperature											
					Characterist	ics						
No	Products	Manufacturer	Current Consumption	Supply Voltage	Power Consumption	Size	Temperature	Price	Interface	Accuracy		
1	M A X 3 0 2 0 5 M	Maxim Integrated	600 μA (typ)	2.7 V to 3.3 V	0.00198	3 x 3 x 0.75 mm	0 C ~ 50 ℃	Qt 1: 1,48 €	2-Wire, I2C	+/- 0.1C		
	TA+							Qt 25:1,39 €				
Rofo	rences	14	[0]	[0]		[0]	[0]	Qt 100: 1,35€	[0]	[0]		
	ps://www.maximinteg	[1] rated.com/en.html	[2]	[2]		[2]	[2]	[2]	[2]	[2]		
			Integrated/MAX3020	05MTA+?as=sGA	EpiMZZMvVdBIXE	aMJhDaKtvJFinZ3HnT	Sa3L6wss%3d					
2	Fever click (MIKROE- 2554)	M ikroElektronika	5 mA	3.3V	0.0165	42.9 x 25.4 mm	0 C ~ 50 ℃	Qt 1:9,02€	GPIO,I2C	0.1°C		
Refe	rences	[1]	[1]	[1]		[1]	[1]	[2]	[1]	[1]		
[1] http	ps://www.mikroe.com	/fever-click										
[2] htt	ps://eu.mouser.com/l					0%252b3ZXT4dPg8k\						
3	BM P180	Bosch Sensortec	32 uA	3 V	0.000096	15 x 13.5 x 2.6 mm	-40℃ ~85℃	Qt 1: \$ 5.70 (4.88 €)	12C	+3.6 Fahrenheit (+2 Celsius)		
	rences	[1]	[2]	[2]		[3]	[2]	[3]	[2]	[3]		
	ps://www.bosch-sens											
					IsrChSOYEGTCcbpl	L13VfRyojs5HQb1tBiU	<u>l%3d_</u>					
	ps://www.addicore.c	om/BM P180-Barome Texas Instruments	tric-Pressure-Sensor- 550 μA	1.62 V to 3.6 V	0.00099	1.5 x 1.5 x 0.675 mm	-40°C ~85℃	Qt 1: 2,11€	I2C	+/- 0.2 C		
4	HDC2010YPA R	rexas instruments	(@VDD=1.8V)	1.02 1 10 3.0 1	0.00033	1.5 x 1.5 x 0.075 1111	-40 0 -030	Qt 10:1,79 € Qt 100: 1,44 €	120	η- 0.2 C		
Refe	rences	[1]	[2] [3]	[2]		[3]	[2]	[2]	[2]	[2]		
[2] htt		ProductDetail/Texas-I s/svmlink/hdc2010.od		YPAR?qs=%2fha	2pyFaduirC4I4MTLE	0dMvZ8xJLYO62tfhV	<u>gNlweY7lcqeYafg</u>	<u>b5g%3d%3d_</u>				
5		Texas Instruments	3.5 µA	1.9 V to 5.5 V	0.00001925	2 x 2 mm	-55℃ to 150℃	Qt 1:2,50 €	I2C	+/- 0.4 C		
	TM P116 NAID RVR							Qt 25:1,61€ Qt 100: 1,36€				
Refe	rences	[1]	[3]	[2]		[3]	[2]	[2]	[2]	[2]		
[2] htt	p://www.ti.com/lit/ds	s/symlink/tmp116.pdf			-	OsZD%2fOGDRwtPY						
6	M LX 90614ES F	ICStation	Typ:1mA Max:2mA	5V	0.005 0.01	19.38 x 11.2 mm (board)	-40℃ ~85℃	Qt 1:\$9.74	PWM, SM Bus	0.5 C		
	rences	[1]	[2]	[1]		[1]	[1]	[1]	[2]	[1]		
		m/mlx90614esf-human										
	ps://www.sparkfun.co	om/datasheets/Senso Silicon Labs	rs/Temperature/SEN- 90 uA	09570-datasheet- 1.9 V ~ 3.6 V	<u>3901090614M005.p</u> 0.000324	-	-40℃ ~ 125℃	Qt 1: 1,95€	12C	+/- 0.1C		
7	SI7051-A20- IM	Silicon Labs	195 nA average current @ 1 Hz	1.9 V ~ 3.6 V	0.0000324	2 x 2 mm	-40℃~125℃	Qt 1: 1,95€ Qt 25:1,78 € Qt 100: 1,62 €	120	+/- 0.10		
Refe	rences	[1]	[2] [3]	[2]		[3]	[2]	[2]	[2]	[2]		
	ps://www.silabs.com/											
[2] htt	ps://eu.mouser.com/f	ProductDetail/Silicon-	Labs/SI7051-A20-IM	?qs=sGAEpiMZZ	Mucentt Sho Snkzps2	5%2fjXuQwESTpp87b	7bFuXOY9MFBsg	<u>1%3d%3d</u>				
[3] htt	ns://eumouser.com/	datasheet/2/368/Si70	50-1-3-4-5-A20-9074	143 ndf								

Table 13. Proposed ECG devices and their characteristics.

Image: Construmption Voitage Construmption Voitage Construmption Voitage 1 Abeging Devices Typ: Trup, tr						ECG				
10 Products Manufacturer Consumption Voltage Consumption Size Temperature Price Interface 1 AB222ACP2 Analog Devices Typ: 10 µ/A 2 V 10 3.5 V 0.000305 Kmmx4 mm -40°C +85°C Cl 12.81°C N/A 1 AD222ACP2 Analog Devices Typ: 10 µ/A 2 V 10 3.5 V 0.000305 Kmmx4 mm -40°C +85°C Cl 12.81°C N/A 1 Max 220 µ/A Analog Devices Typ: 10 µ/A 2 V 10 3.5 V 0.000395 4 x 4 mm -40°C +85°C Cl 12.81°C N/A 1 Max 220 µ/A Analog Devices Typ: 10 µ/A 2 V 10 3.5 V 0.000395 4 x 4 mm -40°C +85°C Cl 12.81°C N/A 1 Max 220 µ/A Analog Devices Typ: 10 µ/A 2 V 10 3.5 V 0.000395 4 x 4 mm -40°C + 85°C Cl 12.81°C N/A 1 Max 220 µ/A Typ: 10 µ/A 1 V 10 0.0004 µ/A 2 N 10 A 0.0004 µ/A 2 N 10 A 0.0004 µ/A 1 N/A 0.0004 µ/A 1 N/A 0.0004 µ/A <th></th> <th></th> <th></th> <th></th> <th>Chara</th> <th>acteristics</th> <th></th> <th></th> <th></th> <th></th>					Chara	acteristics				
1 Mark 200 p.A 0.000005 0.000005 0.000005 of references 1 1 1 0.000005 0.000005 0.000005 of references 1 1 1 1 1 1 1 1 Itera/lows and/op control adapted 12/001 AD023 - 27007 Add Tera/low and/op control adapted 12/001 AD023 - 27007 Add 1	No	Products	Manufacturer		Supply	Power	Size	Temperature	Price	Interface
Image: State of the			Analog Devices	Тур: 170 μА	2 V to 3.5 V	0.000595	4 mm × 4 mm	-40℃ ~85℃	Qt 1:2,81€	N/A
Image: Interpretation of the second	1			Max: 230 µA		0.000805			Qt 25:2,26 €	
Lttp://unwaster.com/Product/Data/Adapter Col									Qt 100:2,06€	
11 Just / Auronaeur and Padul Anton, Decima AD0224.022.872a-sGA EpM ZZM v90 UMM v101 Traveled X4E. 11 Just / Auronaeur and Padul at her / 2/1603.400723.47207.7007.011 11 Just / Auronaeur and Padul Anton. Decima AD0224.022.872a-sGA EpM ZZM v90 UMM v101 Travel Autom 11 Just / Auronaeur and Padul Anton. Decima AD0224.022.872a-sGA EpM ZZM v90 UMM v101 Travel Autom 11 Just / Auronaeur and V20 000 AD0723.47207.701. 11 Just / Auronaeur Andol at her / 2/1603 AD0723.47207.701. 11 Just / Auronaeur Andol at her / 2/1603 AD0723.47207.701. 11 Just / Auronaeur Andol at her / 2/1603 AD0723.47207.701. 11 Just / Auronaeur Andol at her / 2/1603 AD0723.47207.701. 11 Just / Auronaeur Andol at her / 2/1603 AD0723.47207.701. 11 Just / Auronaeur Andol at her / 2/1603 AD0723.47207.701. 11 Just / Auronaeur Andol at her / 2/1603 AD0723.47207.701. 11 Just / Auronaeur Andol Autom Regime AD0724.072.701. 11 Just / Auronaeur Anton Regime AD0724.072.701. 11 Just / Auronaeur Anton Regime AD0724.072.701. 11 Just / Auronaeur Anton Regime AD0724.072.701. 11 Just / Auronaeur Andol Autom Regime AD0724.07	efer	rences	[1]	[3]	[1]		[1]	[1]	[1]	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $										
A DB222ACPZ. Arrang Devices Typ: 170 µA 2 V to 3.5 V 0.000595 4 × 4 mm -40°C - 85°C Q1 1146 € NA ef erences [1] [3] [2]<	-				R7?qs=sGAEpiM	ZZMv9Q1JI0Mo%2ft	Twzkje34X4F			
2 Disk 0] htt				0.111-0.511	0.000505	4 4	1070 0570	0144406	N1/ A
Inter/Annualization 1	2		Analog Devices	Тур: 170 µА	2 V to 3.5 V	0.000595	4 × 4 mm	-40℃~85℃	Qt 1: 1,46 €	N/A
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	efer	rences	[1]	[3]	[2]		[2]	[2]	[2]	
M AX 26 150 EFF Maximitregrated Typ: 340 µA 18 V 0.0055 3.3 x 56 x 13mm 40°C - 89°C C t 3.4 t E IC a M AX 26 150 EFF Max: 720 µA [3] [2] [2]	<u>] htt</u>	ps://eu.mouser.com/F	ProductDetail/Analog-De		<u>RL?qs=sGAEpiM</u>	ZZMv9Q1JI0Mo%2ft	T%252bB6o0WHHfc_			
3 +7 Mac 780 µA 0.0015 eferences (1) (3) (2) (3) (2) (3) eferences (1) (3) (2) (3) (2) (2) (3) Inters/row maximitegrands.com/Poduet Data WM and Integrated UM AX88 S00 - 52822 ndt. (3) (2)				-	1.8 V	0.000612	3.3 x 5.6 x 1.3mm	-40℃ ~85℃	Qt 1:3,41€	I2C
Intro://www.meanintegrated.com/child (b) (c)	3		-			0.00135				
Initipa/Javaar.maximitegrated.com/ani/mail Initipa/Javaar.maximitegrated.com/ani/mail/mail/mail/mail/mail/mail/mail/mai	efer	rences	[1]	[3]	[2]	i	[3]	[2]	[2]	[3]
Intro-//summuter com/datasheet/2/260/MAX80150-2822822.pdl. 4 MAX 3000 3 CT Typ: 77µA 1110 2 V 0.000085 5 x 5 x 0.7 5mm 0 C to + 70°C Cl 1 4 5 4 6 Serial, SPI 6 6 1110 2 V 0.000085 5 x 5 x 0.7 5mm 0 C to + 70°C Cl 1 4 5 4 6 Serial, SPI 1110s//www.meximitegrated.com/sh.ml. 1110 2 V 0.000085 5 x 5 x 0.7 5mm 0 C to + 70°C Cl 1 4 5 4 6 Serial, SPI 1110s//www.meximitegrated.com/sh.ml. 1110s//www.meximitegrated.com/sh.ml. 1110s//www.meximitegrated.com/sh.ml. 1110s//www.meximitegrated.com/sh.ml. 1110s//www.meximitegrated.com/sh.ml. 1110s//www.meximitegrated.com/sh.ml. 1110s//www.meximitegrated.com/sh.ml. 1110s//www.meximitegrated.com/sh.ml. 1110s//www.meximitegrated.com/sh.ml. N/A Series S N/A N/A N/A N/A	http	ps://www.maximintegr				-		•		
4 M AX 30003CT I+* M axim integrated (0 t 0.4,31 €) (0 t 0.4,31 €) (1 t 0.5,11 €) (0 t 0.4,11 €) (1 t 0.5,11 €) (1	<u>] htt</u>	ps://eu.mouser.com/P	roductDetail/Maxim-Inte	grated/MAX86150EF	F+T?qs=%2fha2p	vFaduhRnHfU1QGG4	7Sfo0Nlj3t7nbQaO6P	wr2vkbnBCUXdljg	<u>/////////////////////////////////////</u>	
4 M AX 30003CT I+ 0] htt	ps://eu.mouser.com/d	atasheet/2/256/MAX86	150-1282822.pdf						
efferences [1] [3] [2] [3] [3] [2] [2] [2] Intros/Neuronalizated.com/Enduel Detail/Main-Integrated/MAX30003CTI+2rgs=6GAEpIMZZMIORION/XT3(438XK/AL8r3py/k/2REV/64/83d.d.d.) Intros/Neuronalizated.com/Enduel Detail/Main-Integrated/MAX30003CTI+2rgs=6GAEpIMZZMIORION/XT3(438XK/AL8r3py/k/2REV/64/83d.d.d.) 1 Intros/Neuronalizated.com/Enduel Detail/Main-Integrated/MAX30003-020789.odf. 0.00825 10.5 x 10.5 x 3.45 mm 25C - 75C N/A N/A 6 P52 52 05B Plessey Typ: 15 mA 22.4 V to ±5.5 V 0.00825 10.5 x 10.5 x 3.45 mm 25C - 75C N/A N/A 1 Ntos/Neuronal C2 12.1 kms/neuronalizators.com/ 1 1 13 12.1 kms/neuronalizators.com/ 1 Ntos/Neuronalizators.com/Conductors.com/ Min: 0.6 mA SV 0.003 10 x 10 x 2 mm -25C - 75C QL 1.66.73 € N/A 6 PS2 52 51 Plessey Min: 0.6 mA SV 0.003 10 x 10 x 2 mm -25C - 75C QL 1.66.73 € N/A 1 Min: 0.5 mA SV 0.01 0.01 0.1 x 10 x 2 mm -25C - 75	4		M axim Integrated	Тур: 77µА	1.1to 2 V	0.000085	5 x 5 x 0.7 5mm	0 C to + 70℃	Qt 10:4,31€	Serial, SPI
Inttps://www.maximitegrated.com/onlimit. [12] [21] [22] [23] [24] [24] [25] [26] <t< td=""><td>efer</td><td>rences</td><td>[1]</td><td>[3]</td><td>[2]</td><td>[3]</td><td>[3]</td><td>[2]</td><td></td><td>[2]</td></t<>	efer	rences	[1]	[3]	[2]	[3]	[3]	[2]		[2]
Interview Image: Construction of the second se	- 3] htt	: :ps://eu.mouser.com/d	atasheet/2/256/MAX30	003-1020789.pdf				-	N/A	N/A
Ittp://www.plesseysemiconductors.com/. Ittp://www.plesseysemiconductors.com/ Ittp://www.plesseysemiconductors/PS25251?gassGAEpiMZZM ttKWgNLnZcLrxK%213cZBio4_3 Ittp://www.plesseysemiconductors/PS25251?gassGAEpiMZZM ttKWgNLnZcLrxK%213cZBio4_3 Ittp://www.slabs.com/			· · ·		[3]			[2]		
1) https://eumouser.com/datasheet/2/613/plesseysemiconductors_PS252058-12/5830.pdf. 6 PS25251 Plessey Semiconductors Min: 0.6 mA Typ: 2.0 mA Max: 3.5 mA 5V 0.003 10 x 10 x 2 mm -25°C - 75°C Qt 1: 66,73 € Qt 25:56,83 € Qt 100: 56,13 € eferences [1] [3] [2] [2] [2] [2] [2] 11 http://www.plesseysemiconductors.com/. 2 [2] [2] [2] [2] [2] 2) https://eumouser.com/ProductDetail/Plessey-Semiconductors/PS252517.gs=63AEpiMZZM.ttKWgNLnZoLrxK%g2f3cZBio4_ 3 3 [2] [2] [1] [2]<] http	p://www.plesseysemic								
B Plessey Semiconductors Min: 0.6 mA Typ: 2.0 mA Max: 3.5 mA 5V 0.003 0.01 10 x 10 x 2 mm -25°C - 75°C Qt 1: 66,73 € Qt 25:58,83 € Qt 100: 56,13 € N/A eferences [1] [3] [2]	21 htt	ps://eu.mouser.com/F		miconductors/PS2520)5B?qs=MI2zuikz	5V9BbG4wo4Hs%2f	<u>w=</u>			
6 PS25251 Semiconductors Typ: 2.0 mA Max: 3.5 mA 0.01 0.0175 Qt 2558,83 € Qt 100: 56,13 € eferences [1] [3] [2] [2] [2] [2] [2] Http://www.plesseysemiconductors.com/ Reservemiconductors.com/ Reservemiconductors/PS25251?gs=sGAEpiMZZM1tKWgNLnZcLrxK%213cZBio4. Reservemiconductors/PS25251?gs=sGAEpiMZZM1tKWgNLnZcLrxK%213cZBio4. 1 Siliton Labs N/A 171V to 3.63 V N/A 3.7 x7.0 x 1.1 mm -40°C ~85°C N/A I2C, SPI eferences [1] [2] [2] [2] [1] [1] [1] [1] [1] [1] [1] [1] [1] [1] [1] [1] [1] [1] [2] [2] [1] [1] [1] [2] [2] [1] [2] [2] [1] [1] [1] [2] [2] [3] [2] [2] [3] [2] [3] [2] [3] [2] [3] [2] [2] [3] [2] [3] [2] [3] [2] </td <td></td> <td></td> <td>ToductDetail/Plessey-Se</td> <td></td> <td></td> <td></td> <td></td> <td></td> <td></td> <td></td>			ToductDetail/Plessey-Se							
b PS25257 110, 2.0 HA Max: 3.5 mA 0.017 Qt 203:6.3 ° Qt 100:56,13 € eferences [1] [3] [2] [2] [2] [2] [2] Intp://www.plesseysemiconductors.com/. PS25251 [3] [2	- 3] htt	ps://eu.mouser.com/d			205B-1215830.pd	<u>lf_</u>				
Image: Problem 1 [1] [3] [2] [3] [2] [3] [2] [3] [3] [3] [3] [3] [3] [3] [3] [3] [3] [2] [3]	- 8] htt	ps://eu.mouser.com/d	atasheet/2/613/plesseys Plessey	emiconductors PS25			10 x 10 x 2 mm	-25℃ ~ 75℃	Qt 1:66,73 €	N/A
Intro//www.plesseysemiconductors.com/. (c)			atasheet/2/613/plesseys Plessey	Min: 0.6 mA		0.003	10 x 10 x 2 mm	-25℃ ~75℃		N/A
$\frac{1}{2} https://eumouser.com/2foductDetail/Pessey-Semiconductors/PS25251?qs=sGAEpiMZZM1tKWqNLnZcJrxK%2f3cZBio4.$ $\frac{1}{2} https://eumouser.com/datasheet/2/6f3/ps25251-epic-qfn-sensor-electrophysiology-high-gai-f218582.pdf.$ $\frac{7 Si1171}{1} Silicon Labs N/A 171V to 3.63 V N/A 3.7 x 7.0 x 1.1 mm -40°C ~ 85°C N/A 12C, SPI efferences [1] [2] [1] [1] [1] [1] [1] [2] [2] [2] [1] [1] [1] [2] [2] [2] [1] [1] [1] [2] [2] [2] [2] [1] [1] [1] [2] [2] [2] [2] [2] [2] [2] [2] [2] [2$			atasheet/2/613/plesseys Plessey	Min: 0.6 mA Typ: 2.0 mA		0.003 0.01	10 x 10 x 2 mm	-25℃ ~ 75℃	Qt 25:58,83 €	N/A
7Si 1171Silicon LabsN/A1.71V to 3.63 VN/A3.7 × 7.0 × 1.1 mm-40°C ~ 85°CN/AI2C, SPIeferences[1][2][2][1][1][1][1][1][1][1]1Ittps://www.silabs.com/.2] https://www.silabs.com/2] https://www.silabs.com/ocuments/public/data-shorts/si1171-short.pdf8] $ADS1293RIZXTexas Instruments500 uA1.65 V to 3.6 V0.00188.00 × 8.00 mm-40°C ~ 85°CQt 1: 22,46 €Serial, SPIeferences[1][3][2][3][2][2][2][2][2][2]1[1][3][2][3][2][2][2][2][2][2]9M icro ECG[1]N/A3.3 VN/A22 X 26 X 16 mmN/AQt 1: $ 11.00UART, BLeferences[1][1][1][1][1][1][1][1][1][1]$	6	PS25251	atasheet/2/613/plesseys Plessey Semiconductors	min: 0.6 mA Typ: 2.0 mA Max: 3.5 mA	5V	0.003 0.01			Qt 25:58,83 € Qt 100: 56,13 €	N/A
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Intps://www.silabs.com/ Image: Carrier of the car	6 efer [http 2] htt	PS25251 rences p://www.plesseysemic ps://eu.mouser.com/F	atasheet/2/613/plesseys Plessey Semiconductors [1] onductors.com/_ roductDetail/Plessey-Se atasheet/2/613/ps25251	min: 0.6 mA Typ: 2.0 mA Max: 3.5 mA [3] miconductors/PS2525 epic-gfn-sensor-elect	5V [2] 51? qs=sGA EpiM Z rophysiology-hig	0.003 0.01 0.0175 ZM ttKWgNLnZcJrxK h-gai-1218582.pdf.	[2] %2f3cZBio4_	[2]	Qt 25:58,83 € Qt 100: 56,13 € [2]	
22 https://www.silabs.com/documents/public/data-shorts/sil171-short.pdf 32 https://www.silabs.com/products/sensors/biometric/sil17x. 8 $ADS1298RI2X$ Texas Instruments 500 uA 1.65 V to 3.6 V 0.0018 8.00 × 8.00 mm -40°C ~ 85°C Qt 1: 22,46 € Serial, SPI eferences [1] [3] [2] [3] [2] [2] [2] Lhttp://www.ti.com/ 21 https://eumouser.com/ProductDetail/Texas-Instruments/ADS1298RIZXGR2qs=sGAEpiMZZM sj2w6QBC0lcqxQtqDcAlcV_ 31 http://www.ti.com/lit/ds/symlink/ads1298r.pdf 9 M icro ECG ITEAD N/A 3.3 V N/A 22 X 26 X 16 mm N/A Qt 1: \$ 11.00 UART, BL eferences [1] [1] [1] [1] [1] [1] [1] [1] [1] [1]	6 efer [_http 2]_htt 3]_htt	PS25251 rences p://www.plesseysemic ps://eu.mouser.com/F ps://eu.mouser.com/d	atasheet/2/613/plesseys Plessey Semiconductors [1] onductors.com/_ roductDetail/Plessey-Se atasheet/2/613/ps25251	min: 0.6 mA Typ: 2.0 mA Max: 3.5 mA [3] miconductors/PS2525 epic-gfn-sensor-elect	5V [2] 51? qs=sGA EpiM Z rophysiology-hig	0.003 0.01 0.0175 ZM ttKWgNLnZcJrxK h-gai-1218582.pdf.	[2] %2f3cZBio4_	[2]	Qt 25:58,83 € Qt 100: 56,13 € [2]	
8 $ADS 1293RIZX$ CPTexas Instruments500 uA1.65 V to 3.6 V0.00188.00 × 8.00 mm-40°C ~ 85°CQt 1: 22,46 €Serial, SPIeferences[1][3][2][3][2][3][2][2][2](http://www.ti.com/22 X 26 X 1.6 mmN/A $22 X 26 X 1.6 mm$ N/A $Qt 1: 11.00 UART, BL9Micro ECG[1][1][1][1][1][1][1][1][1]	6 efer 1 http 2 htt 3 htt 7 efer	PS25251 p://www.plesseysemic ps://eu.mouser.com/F ps://eu.mouser.com/d Si1171 rences	It asheet/2/613/plesseys Semiconductors [1] conductors.com/_ ProductDetail/Plessey-Se at asheet/2/613/ps25251 Silicon Labs [1]	min: 0.6 mA Typ: 2.0 mA Max: 3.5 mA [3] miconductors/PS2525 epic-gfn-sensor-elect	5V [2] iti2 gs=sGAEpiMZ trophysiology-hig 1.71 V to 3.63 V	0.003 0.01 0.0175 ZM ttKWgNLnZcJrxK h-gai-1218582.pdf.	[2] %2f3cZBio4_ 3.7 × 7.0 × 1.1 mm	[2] -40°C - 85°C	Qt 25:58,83 € Qt 100: 56,13 € [2]	12C, SPI
8 700 Texas instruments 500 uA 1.65 V to 3.6 V 0.0018 8.00 X 8.00 mm -40°C - 85°C Qt 1:22,40°C Serial, SPI eferences [1] [3] [2] [3] [2] <td< td=""><td>6 efer [. http 2] htt 3] htt 7 efer [. http</td><td>PS2 52 51 rences p://www.plesseysemic ps://eu.mouser.com/f ps://eu.mouser.com/d Si1171 rences ps://www.silabs.com/</td><td>atasheet/2/613/plesseys Plessey Semiconductors [1] conductors.com/ product Detail/Plessey-Se atasheet/2/613/ps25251 Silicon Labs [1]</td><td>min: 0.6 mA Typ: 2.0 mA Max: 3.5 mA [3] miconductors/PS252: -epic-gfn-sensor-elect N/A</td><td>5V [2] it2 gs=sGAEpiMZ trophysiology-hig 1.71 V to 3.63 V [2]</td><td>0.003 0.01 0.0175 ZM ttKWgNLnZcJrxK h-gai-1218582.pdf.</td><td>[2] %2f3cZBio4_ 3.7 × 7.0 × 1.1 mm</td><td>[2] -40°C - 85°C</td><td>Qt 25:58,83 € Qt 100: 56,13 € [2]</td><td>12C, SPI</td></td<>	6 efer [. http 2] htt 3] htt 7 efer [. http	PS2 52 51 rences p://www.plesseysemic ps://eu.mouser.com/f ps://eu.mouser.com/d Si1171 rences ps://www.silabs.com/	atasheet/2/613/plesseys Plessey Semiconductors [1] conductors.com/ product Detail/Plessey-Se atasheet/2/613/ps25251 Silicon Labs [1]	min: 0.6 mA Typ: 2.0 mA Max: 3.5 mA [3] miconductors/PS252: -epic-gfn-sensor-elect N/A	5V [2] it2 gs=sGAEpiMZ trophysiology-hig 1.71 V to 3.63 V [2]	0.003 0.01 0.0175 ZM ttKWgNLnZcJrxK h-gai-1218582.pdf.	[2] %2f3cZBio4_ 3.7 × 7.0 × 1.1 mm	[2] -40°C - 85°C	Qt 25:58,83 € Qt 100: 56,13 € [2]	12C, SPI
Intp://www.ti.com/ Image: Calify and	6 efer <u>0 http</u> 2 <u>1 htt</u> 7 efer <u>0 http</u> 2 <u>1 htt</u>	PS25251 rences p://www.plesseysemic ps://eu.mouser.com/F ps://eu.mouser.com/f Si1171 rences ps://www.silabs.com/ ps://www.silabs.com/ ps://www.silabs.com/	atasheet/2/613/plesseys Plessey Semiconductors [1] conductors.com/_ roductDetail/Plessey-Se atasheet/2/613/ps25251 Silicon Labs [1] documents/public/data-	emiconductors PS25 Min: 0.6 mA Typ: 2.0 mA Max: 3.5 mA [3] miconductors/PS252 epic-qfn-sensor-elect N/A shorts/si1171-short.pd	5V [2] it2 gs=sGAEpiMZ trophysiology-hig 1.71 V to 3.63 V [2]	0.003 0.01 0.0175 ZM ttKWgNLnZcJrxK h-gai-1218582.pdf.	[2] %2f3cZBio4_ 3.7 × 7.0 × 1.1 mm	[2] -40°C - 85°C	Qt 25:58,83 € Qt 100: 56,13 € [2]	12C, SPI
Bittp://eumouser.com/ProductDetail/Texas-Instruments/ADS1298RIZXGR?qs=sGAEpiMZZMsj2w6QBC0lcqxQtqDcAlcV 9 Micro ECG ITEAD N/A 3.3 V N/A 22 X 26 X 1.6 mm N/A Qt 1: \$ 11.00 (9, 43 9) UART, BL eferences [1] [1] [1] [1] [1] [1] [1] [1]	6 efer 1 http 2] htt 7 efer 1 http 2] htt 3] htt 3] htt	PS25251 rences p://www.plesseysemic ps://eu.mouser.com/F ps://eu.mouser.com/f Si1171 rences ps://www.silabs.com/ ps://www.silabs.com/ ps://www.silabs.com/	atasheet/2/613/plesseys Plessey Semiconductors [1] conductors.com/_ troductDetail/Plessey-Se atasheet/2/613/ps25251 Silicon Labs [1] documents/public/data= products/sensors/biome	emiconductors PS25 Min: 0.6 mA Typ: 2.0 mA Max: 3.5 mA [3] miconductors/PS2525 epic-qfn-sensor-elect N/A shorts/si1171-short.pd stric/si117x.	5V [2] 512 gs=sGA EpiMZ trophysiology-hig 1.71 V to 3.63 V [2] f.	0.003 0.01 0.0175 ZMttKWgNLnZcJrxK h-gai-1218582.pdf_ N/A	[2] %2f3cZBio4_ 3.7 x7.0 x 1.1mm [2]	[2] -40°C - 85°C [1]	Qt 25:58,83 € Qt 100: 56,13 € [2] N/A	12C, SPI
9 Micro ECG ITEAD N/A 3.3 V N/A 22 X 26 X 16 mm N/A Qt 1.\$11.00 (9,43 €) UART, BL eferences [1]	6 efer <u>http</u> <u>2</u> <u>htt</u> 7 efer <u>0</u> <u>http</u> <u>2</u> <u>htt</u> <u>8</u> <u>htt</u> 8 <u><u>htt</u> 8<u></u>efer</u>	PS25251 rences p://www.plesseysemic ps://eu.mouser.com/F ps://eu.mouser.com/f ps://www.silabs.com/ Ps://www.silabs	atasheet/2/613/plesseys Plessey Semiconductors [1] conductors.com/ troductDetail/Plessey-Se atasheet/2/613/ps25251 Silicon Labs [1] documents/public/data- products/sensors/biome Texas Instruments	miconductors_PS25 Min: 0.6 mA Typ: 2.0 mA Max: 3.5 mA [3] miconductors/PS2525 epic-gfn-sensor-elect N/A N/A shorts/si1171-short.pd atric/si117x. 500 uA	5V [2] 512 gs=sGAEpiMZ trophysiology-hig 1.71 V to 3.63 V [2] f. 1.65 V to 3.6 V	0.003 0.01 0.0175 ZMttKWgNLnZcJrxK h-gai-1218582.pdf_ N/A	[2] %2f3cZBio4_ 3.7 x 7.0 x 1.1 mm [2] 8.00 x 8.00 mm	[2] -40°C ~ 85°C [1] -40°C ~ 85°C	Qt 25:58,83 € Qt 100: 56,13 € [2] N/A Qt 1: 22,46 €	12C, SPI [1]
9 Micro ECG (9,43 €) eferences [1] [1] [1] [1] [1]	6 efer [.http 2].htt 3].htt 7 efer [.http 8].htt 8 efer [.http	PS25251 rences p://www.plesseysemic ps://eu.mouser.com/F ps://eu.mouser.com/F ps://eu.mouser.com/f ps://www.silabs.com/ ps://www.silabs.com/ ADS1298R12X rences p://www.ti.com/	atasheet/2/613/plesseys Plessey Semiconductors [1] conductors.com/ troductDetail/Plessey-Se atasheet/2/613/ps25251 Silicon Labs [1] documents/public/data- products/sensors/biome Texas Instruments [1]	miconductors_PS25 Min: 0.6 mA Typ: 2.0 mA Max: 3.5 mA [3] miconductors/PS2525 epic-gfn-sensor-elect N/A shorts/si1171-short.pd atric/si117x. 500 uA [3]	5V [2] 512 gs=sGAEpiMZ trophysiology-hig 1.71 V to 3.63 V [2] 1.65 V to 3.6 V [2]	0.003 0.01 0.0175 ZM tt KWgNLnZcJrxK h-gai-1218582.pdf. N/A	[2] %2f3cZBio4_ 3.7 × 7.0 × 1.1 mm [2] 8.00 × 8.00 mm [3]	[2] -40°C ~ 85°C [1] -40°C ~ 85°C	Qt 25:58,83 € Qt 100: 56,13 € [2] N/A Qt 1: 22,46 €	I2C, SPI [1] Serial, SPI
eferences [1] [1] [1] [1] [1]	6 efer 0. http 2]. htt 3]. htt 7 efer 0. http 2]. htt 8 efer 0. http 2]. htt	PS25251 rences p://www.plesseysemic ps://eu.mouser.com/E ps://eu.mouser.com/E ps://www.silabs.com/ ps://www.silab	atasheet/2/613/plesseys Plessey Semiconductors [1] conductors.com/_ roductDetail/Plessey-Se atasheet/2/613/ps25251 Silicon Labs [1] documents/public/data- products/sensors/biome Texas Instruments [1] roductDetail/Texas-Instr (symlink/ads1298r.pdf	emiconductors_PS25 Min: 0.6 mA Typ: 2.0 mA Max: 3.5 mA [3] miconductors/PS2525 epic-gfn-sensor-elect N/A shorts/si1171-short.pd atric/si117x. 500 uA [3] uments/ADS1298RIZ	5V [2] 51? qs=sGA EpiM Z rrophysiology-hig 1.71 V to 3.63 V [2] 1.65 V to 3.6 V [2] XGR?qs=sGA Epi	0.003 0.01 0.0175 ZM tt KWgNLnZcJrxK h-gai-1218582.pdf. N/A 0.0018 MZZM sj2w6QBC0/c	[2] %2f3cZBio4_ 3.7 × 7.0 × 1.1 mm [2] 8.00 × 8.00 mm [3] gxQtqDcAlcV_	[2] -40°C - 85°C [1] -40°C - 85°C [2]	Qt 25:58,83 € Qt 100: 56,13 € [2] N/A Qt 1: 22,46 € [2]	I2C, SPI [1] Serial, SPI [2]
	6 efer 0. http 2.] htt 3.] htt 7 efer 0. http 2.] htt 8 efer 0. http 2.] htt 8 efer 0. http 2.] htt	PS2 52 51 rences p://www.plesseysemic ps://eu.mouser.com/F ps://eu.mouser.com/d Si1171 rences ps://www.silabs.com/ ps://www.silabs.c	atasheet/2/613/plesseys Plessey Semiconductors [1] conductors.com/_ roductDetail/Plessey-Se atasheet/2/613/ps25251 Silicon Labs [1] documents/public/data- products/sensors/biome Texas Instruments [1] roductDetail/Texas-Instr (symlink/ads1298r.pdf	emiconductors_PS25 Min: 0.6 mA Typ: 2.0 mA Max: 3.5 mA [3] miconductors/PS2525 epic-gfn-sensor-elect N/A shorts/si1171-short.pd atric/si117x. 500 uA [3] uments/ADS1298RIZ	5V [2] 51? qs=sGA EpiM Z rrophysiology-hig 1.71 V to 3.63 V [2] 1.65 V to 3.6 V [2] XGR?qs=sGA Epi	0.003 0.01 0.0175 ZM tt KWgNLnZcJrxK h-gai-1218582.pdf. N/A 0.0018 MZZM sj2w6QBC0/c	[2] %2f3cZBio4_ 3.7 × 7.0 × 1.1 mm [2] 8.00 × 8.00 mm [3] gxQtqDcAlcV_	[2] -40°C - 85°C [1] -40°C - 85°C [2]	Qt 25:58,83 € Qt 100: 56,13 € [2] N/A Qt 1: 22,46 € [2] Qt 1: \$ 11.00	I2C, SPI [1] Serial, SPI
1 https://www.iteed.co/micro.cog.html	6 efer] http 2] htt 3] htt 7 efer] http 2] htt 8 efer] http 2] htt 8 efer] http 2] htt 8 9	PS25251 rences p://www.plesseysemic ps://eu.mouser.com/F ps://eu.mouser.com/G Si1171 rences ps://www.silabs.com/ ps://www.silabs.com/ ps://www.silabs.com/ ps://www.ticom/ ps://www.ticom/iti/ds Micro ECG	atasheet/2/613/plesseys Plessey Semiconductors [1] onductors.com/_ roductDetail/Plessey-Se atasheet/2/613/ps25251 Silicon Labs [1] documents/public/data= products/sensors/biomer Texas Instruments [1] roductDetail/Texas-Instr /symlink/ads1298r.pdf ITEAD	emiconductors_PS25 Min: 0.6 mA Typ: 2.0 mA Max: 3.5 mA [3] miconductors/PS2525 epic-gfn-sensor-elect N/A shorts/si1171-short.pd atric/si117x. 500 uA [3] uments/ADS1298RIZ	5V [2] 51? qs=sGAEpiM Z rophysiology-hig 1.71 V to 3.63 V [2] f. 1.65 V to 3.6 V [2] X GR?qs=sGAEpi 3.3 V	0.003 0.01 0.0175 ZM tt KWgNLnZcJrxK h-gai-1218582.pdf. N/A 0.0018 MZZM sj2w6QBC0/c	[2] %2f3cZBio4_ 3.7 × 7.0 × 1.1 mm [2] 8.00 × 8.00 mm [3] cxQtqDcAlcV_ 22 × 26 × 1.6 mm	[2] -40°C - 85°C [1] -40°C - 85°C [2]	Qt 25:58,83 € Qt 100: 56,13 € [2] N/A Qt 1: 22,46 € [2] Qt 1: 22,46 € [2] Qt 1: \$ 11.00 (9,43 €	I2C, SPI [1] Serial, SPI [2] UART, BLE

Table 14. Proposed accelerometer devices and characteristics details.

	Accelerometer										
				c	haracteristics						
No	Products	Manufacturer	Current Consumption	Supply Voltage	Power Consumption	Size	Temperature	Price	Interface	Range	
1	MPU 9255	InvenSense Inc.	3.2 mA	2.4 V – 3.6 V	0.01152	3 x 3 x1mm	-40°C to 85°C	N/A	12C	±4800µT	
Refer	ences	[1]	[1]	[2]		[2]	[1]		[1]	[2]	
			-products/products/mpu-9255-			-3-axis-magnetomet	ter_				
			es/MPU-9255-Datasheet.pdf?24								
	s://www.amazon.com/UC	-	55-compass-Accelerometer-Gyro								
2	AIS1120SXTR	STM icroelectronic	6 mA	3.13 V to 3.47 V	0.02082	4.9 x 6 x 1.75 mm	-40 ℃ to +105 ℃	Qt 1: 5,21€ Qt 10:4,43 € Qt 100: 3,84 €	SPI	Full-scale range: ±114	
Refer	ences	[1]	[3]	[2]		[3]	[2]	[2]	[2]	[3]	
[1] https://www.st.com/ [2] https://eu.mouser.com/ProductDetail/STM icroelectronics/AIS1120SXTR?gs=%2fha2pyFadujz3jmjWPaCWwe%2fGhuiR%252bh1N1UF0YLynZaVbrT%2fVdyNt0%2d%2d_ [3] https://eu.mouser.com/datasheet/2/389/ais1120sx-1078943.pdf_											
3		STM icroelectronic	10 µA	2.16 V to 3.6 V	0.000036	3 x 3 x1.0 mm	-40°C to 85°C	Qt 1:8,94 €	I2C, SPI	full scales of ±100g/	
	H3LIS331DLTR							Qt 25:7,71€		±200g/±40g	
								Qt 100:6,69€			
Refer	ences	[1]	[2]	[2]		[3]	[2]	[2]	[2]	[3]	
[1] http	s://www.st.com/_										
[2] http	s://eu.mouser.com/Proc	luctDetail/STM icroel	ectronics/H3LIS331DLTR?qs=s0	GA EpiM ZZM tlnW	hFp5JOwGi5lG47hw0	<u>)p</u>					
[3] http	os://eu.mouser.com/data	sheet/2/389/h3lis33	<u>1dl-954720.pdf</u>								
4	ADXL335BCPZ	Analog Devices	350 uA	1.8 V to 3.6 V	0.00126	4 x 4 x 1.45 mm	-40 ℃ to +85 ℃	Qt 1: 4,67 € Qt 25:3,95 € Qt 100: 3,53 €	N/A	Full-scale range: ±3 g	
Refer	ences	[1]	[2]	[2]		[3]	[2]	[2]		[3]	
[2] http	://www.analog.com/en/ii ps://eu.mouser.com/Proc ps://eu.mouser.com/data	luctDetail/Analog-De sheet/2/609/ADXL3		-				_	_		
5	EVAL-ADXL335Z	Analog Devices	350 µA	1.8 V to 3.6 V	0.00126	4 x 4 mm	-40 ℃ to +105 ℃	Qt 1:33,58 €	N/A	Full-scale range: ±3 g	
Refer		[1]	[3]	[3]		[2]	[3]	[2]		[3]	
[2] http	://www.analog.com/en/ii ps://eu.mouser.com/Proc ps://eu.mouser.com/data	luctDetail/Analog-De sheet/2/609/ADXL3									
6	101020051	Seeed Studio	350 µA @ 3V	3 V to 5 V	0.00105	4 x 4 x 1.45 mm	N/A	Qt 1:8,12 €	N/A	Full-scale range: ±3 g	
Refer		[1]	[3]	[2]		[3]		[2]		[3]	
[2] http	s://www.seeedstudio.co ps://eu.mouser.com/Proc ps://eu.mouser.com/data	luctDetail/Seeed-Stur sheet/2/744/Seeed	dio/101020051?qs=sGAEpiMZZ 101020051-1217452.pdf					_	_		
7	MMA8452QR1	NXP / Freescale	6 μA to 165 μA	1.95 V to 3.6 V	0.0000117 to 0.000594	3 x 3 x 1mm	-40 ℃ to 85℃	Qt 1: 2,17 € Qt 25:1,49 € Qt 100: 1,15 €	12C	full scales of ±2 g/±4 g/±8 g	
Refer	ences	[1]	[3]	[2]		[3]	[2]	[2]	[2]	[3]	
[2] http			scale/MMA8452QR1?qs=sGAE	piMZZMs5J6Fwf	w6CO1HjGVnOExhk						
	os://eu.mouser.com/data			1001/1 00:0	0.000056.1	0.0.0.0	4000 0000	0140000		0	
8	BM A400	Bosch Sensortec	Max. perform.: 14 μA Typical use case: <8 μA Low power use case: <4 μA	1.62 V to 3.6 V	0.0000504 0.0000288 0.0000144	2 x 2 x 0.65 m ³	-40℃~85℃	Qt 1: 3,00 € Qt 25:1,93 € Qt 100: 1,63 €	SPI, I2C	±2 g, ±4 g, ±8 g, ±16 g	
Refer		[1]		[1]		[1]	[1]	[2]	[1]	[1]	
			/all_products/bma400_1 ch-sensortec/BMA456/828-107	5-1-ND/7401320							